LM5036 Half-Bridge PWM Controller with Integrated Auxiliary Bias Supply

1 Features

- High Integration Controller for Small Form Factor, High-Density DC-DC Power Converters
- Integrated 100-V, 100-mA Auxiliary Bias Supply
- Voltage-Mode Control with Input Voltage Feed-Forward
- 100-V High-Voltage Start-Up Regulator
- Fully Regulated Pre-Biased Start-Up
- Enhanced Cycle-By-Cycle Current Limiting with Pulse Matching
- Optimized Maximum Duty Cycle for Primary-Side FETs
- Configurable Latch, OVP Operation
- Integrated 100-V, 2-A MOSFET Drivers for Primary-Side FETs
- Programmable Dead-Time Between Primary-Side and Synchronous Rectifier (SR) FETs
- Create a Custom Design Using the LM5036 with the WEBENCH® Power Designer

2 Applications

- Telecom and Data Communication Isolated Power Supplies
- Industrial Power Supplies

3 Description

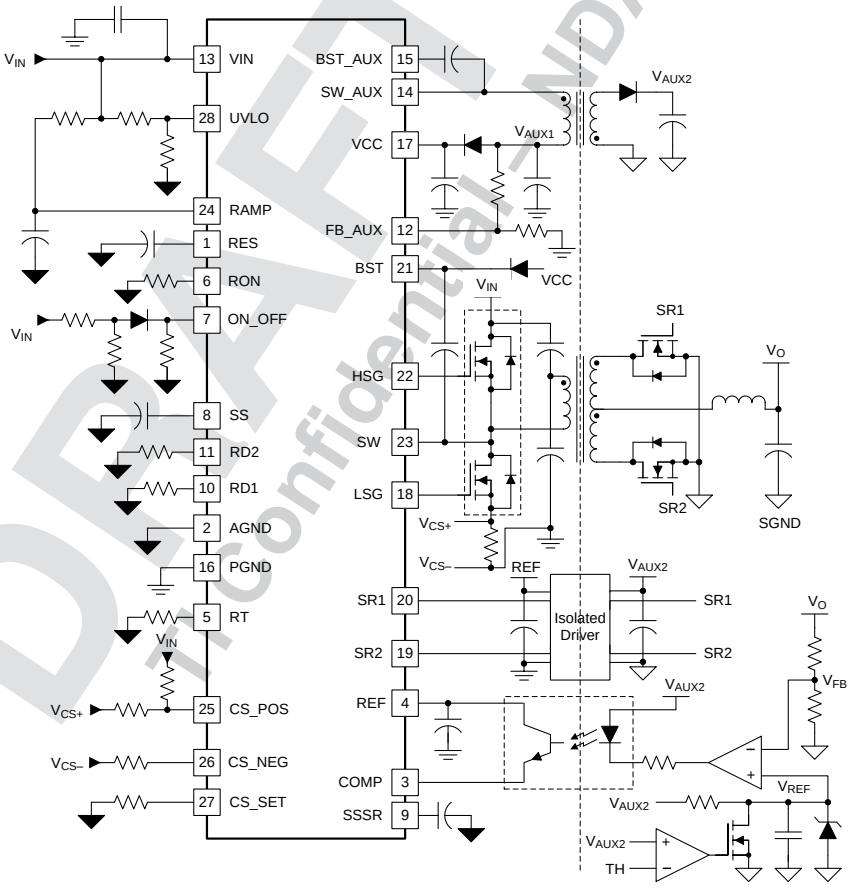
The LM5036 device is a highly integrated PWM controller with integrated auxiliary bias supply which offers high power density for telecom, datacom and industrial power converter applications. It contains all of the features necessary to implement half-bridge topology power converters using voltage-mode control with input voltage feed-forward. This device is intended to operate on the primary side of an isolated DC-DC power converter with input voltage up to 100 V.

Device Information(1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
LM5036	WQFN (28)	5.00 mm × 5.00 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Simplified Application



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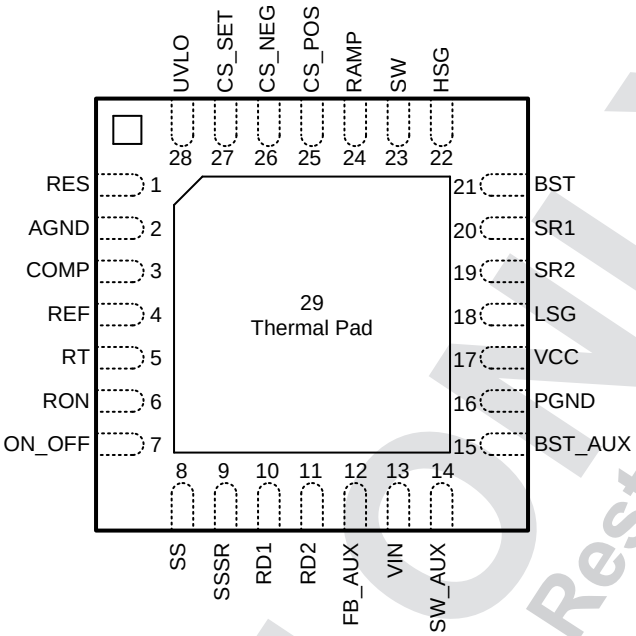
4 Revision History

DATE	REVISION	NOTES
May 2018	A	First public release.

5 Pin Configuration and Functions

RJB Package
28-Pin WQFN
Top View



Pin Functions

PIN		I/O(1)	DESCRIPTION
NAME	NO.		
AGND	2	G	Analog ground
BST	21	I	Half-bridge high-side gate drive bootstrap
BST_AUX	15	I	Auxiliary supply high-side gate drive bootstrap
COMP	3	I	Control current input to half-bridge PWM comparator
CS_NEG	26	I	Current sense amplifier negative input terminal
CS_POS	25	I	Current sense amplifier positive input terminal
CS_SET	27	I	Current limit setting
FB_AUX	12	I	Auxiliary supply output voltage feedback
HSG	22	O	Half-bridge high-side MOSFET output driver
LSG	18	O	Half-bridge low-side MOSFET output driver
ON_OFF	7	I	Configurable for over voltage protection (OVP) or latch mode
PGND	16	G	Power ground
RAMP	24	I	RAMP signal input to half-bridge PWM comparator
RD1	10	I	Synchronous rectifier trailing-edge delay
RD2	11	I	Synchronous rectifier leading-edge delay
REF	4	O	5-V reference regulator output
RES	1	I	Hiccup mode restart timer
RON	6	I	Auxiliary supply on-time control
RT/SYNC	5	I	Oscillator frequency control or external clock synchronization
SR1	20	O	Synchronous rectifier PWM control output
SR2	19	O	Synchronous rectifier PWM control output
SS	8	I	Soft-start input

(1) I = input, O = output, G = ground

Pin Functions (continued)

PIN		I/O(1)	DESCRIPTION
NAME	NO.		
SSSR	9	I	Synchronous rectifier soft-start input
SW	23	I	Half-bridge switch node
SW_AUX	14	I	Auxiliary supply switch node
UVLO	28	I	Input undervoltage lockout
VCC	17	I	Bias supply
VIN	13	I	Input voltage
Pad	29	G	Exposed thermal pad

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

	MIN	MAX	UNIT
VIN to GND	-0.3	105	V
SW/SW_AUX to GND	-5	105	V
BST TO SW, BST_AUX TO SW_AUX	-0.3	16	V
HSG to SW	-0.3	16	V
LSG to GND	-0.3	16	V
SR1/SR2 to GND	-0.3	5	V
VCC to GND	-0.3	16	V
RT, UVLO, ON/OFF, RON, RAMP, RES, FB_AUX, CS_POS, CS_NEG, CS_SET to GND	-0.3	5	V
COMP to GND		-0.3	V
COMP Input Current		10	mA
Junction Temperature		150	ºC
Storage Temperature, Tstg	-55	150	ºC

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins(1)	±2000	V
		Charged device model (CDM), per JEDEC specificationJESD22-C101, all pins(2)	±750	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V_{IN}	Input voltage	18		100	V
External V_{CC}	Supply Voltage	8.5		14	V
T_J	Junction Temperature	–40		125	°C

6.4 Thermal Information

THERMAL METRIC (1)		LM5036 RJB (WQFN) 28 PINS	UNIT
$R_{\Theta JA}$	Junction-to-ambient thermal resistance	29.9	°C/W
$R_{\Theta JC(top)}$	Junction-to-case (top) thermal resistance	18.2	°C/W
$R_{\Theta JB}$	Junction-to-board thermal resistance	10.4	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	0.2	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	10.3	°C/W
$R_{\Theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	1	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics application report* .

6.5 Electrical Characteristics

MIN and MAX limits apply the junction temperature range of –40°C to 125°C. Unless otherwise specified, the following conditions apply: V_{IN} = 48 V, R_T = 25 kΩ, RD_1 = RD_2 = 20 kΩ, R_{ON} =100 kΩ. No load on LSG, HSG, SR1, SR2, UVLO = 2.5 V, ON_OFF = 0 V.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
START-UP REGULATOR						
V_{CC}	Vcc voltage	I_{CC} = 10 mA	7.5	7.8	8.1	V
$I_{CC\ (Lim)}$	Vcc current limit	V_{CC} = 6 V, V_{IN} = 20 V	69	81	94	mA
$I_{CC(ext)}$	Vcc supply current	Supply current into Vcc from an externally applied source. V_{CC} = 9 V, FB_AUX = 0 V	6.6	9	11	mA
$V_{CC(reg)}$	Vcc load regulation	I_{CC} from 0 to 50 mA	31	49	73	mV
$V_{CC(UV)}$	Vcc undervoltage threshold	Positive going Vcc	7.4	7.7	8.0	V
		Negative going Vcc	6.1	6.3	6.7	V
	V_{IN} shutdown current	V_{IN} = 20 V, V_{UVLO} = 0 V, R_{ON} = 100 kΩ	276	580	670	µA
		V_{IN} = 100 V, V_{UVLO} = 0 V, R_{ON} = 100 kΩ	299	600	717	µA
	V_{IN} start-up regulator leakage	V_{CC} = 9 V, applied externally, FB_AUX > 2 V, SS = 0 V, R_{ON} = 100 kΩ	180	234	304	µA
VOLTAGE REFERENCE REGULATOR (REF PIN)						
V_{REF}	REF voltage	I_{REF} = 0 mA	4.85	5	5.15	V
$V_{REF(REG)}$	REF load regulation	I_{REF} = 0 to 25 mA	24	37	57	mV
$I_{REF(LIM)}$	REF current limit	V_{REF} = 4.5 V, V_{IN} = 20 V	28	39	47	mA
$V_{REF(UV)}$	REF undervoltage threshold	Positive going V_{REF}	4.3	4.5	4.7	V
	Hysteresis		0.16	0.26	0.37	V
UNDERVOLTAGE LOCK OUT AND SHUTDOWN (UVLO PIN)						
V_{UVLO}	UVLO threshold		1.205	1.25	1.305	V
I_{UVLO}	UVLO Hysteresis current		15	20	24	µA
V_{SD}	Internal startup regulator enable threshold	SS = 0 V, FB_AUX = 2.5 V	0.34	0.38	0.41	V
	Hysteresis		90	135	175	mV
ON_OFF PIN						
V_{ON_OFF}	ON_OFF threshold		1.18	1.25	1.32	V
	ON_OFF hysteresis current		40	50	60	µA
SOFT-START (SS PIN, SSSR PIN)						
I_{SS}	SS charge current	SS = 0 V	17	20	24	µA
	SS threshold to enable SSSR charge current	I_{COMP} < 800 µA	1.93	2.06	2.2	V

Electrical Characteristics (continued)

MIN and MAX limits apply the junction temperature range of –40°C to 125°C. Unless otherwise specified, the following conditions apply: V_{IN} = 48 V, R_T = 25 kΩ, RD_1 = RD_2 = 20 kΩ, R_{ON} =100 kΩ. No load on LSG, HSG, SR1, SR2, UVLO = 2.5 V, ON_OFF = 0 V.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
	SS output low voltage	Sinking 100 µA	30	48	57	mV
	SS threshold to disable switching		865	1000	1198	mV
I_{SSSR}	SSSR charge current	SS > 2 V, I_{COMP} < 800 µA	17	20	24	µA
	SSSR output low voltage	Sinking 100 µA	30	38.7	49	mV
	SSSR threshold to enable SR freewheeling pulse		0.65	1.17	1.67	V
CURRENT SENSE (CS_POS, CS_NEG, and CS_SET PIN)						
V_{LIM}	Current limit setting voltage		0.72	0.75	0.77	V
	Ratio of internal negative to positive current limit threshold		0.3	0.58	0.9	
t_{CSLSG}	CS to gate driver output delay		60	85	122	ns
t_{CSBLK}	CS leading-edge blanking		33	53	76	ns
K_{CBC1} (1)	V_{LIM} x (K_{2a} X K_{10b} - K_{10a})	At CBC trip threshold	7.28	7.51	7.81	V
$V_{CSOffset}$ (1)	V_{CS_POS} - V_{CS_NEG}	At CBC trip threshold	-0.63	-0.02	0.32	mV
$I_{BiasOffset}$ (1)	$I_{BiasPOS}$ - $I_{BiasNEG}$	At CBC trip threshold	-0.67	0.02	0.29	µA
I_{SLOPE} (1)	Peak value of current source for slope compensation		50	54	59	µA
REVERSE CURRENT PROTECTION						
N	Number of switching periods to reset negative over-current event counter			4		
SR_CTR_TH	SSSR threshold to reset SSSR cap clamp event counter		4.8	4.94	5.1	V
HICCUP MODE (RES PIN)						
R_{RES}	RES pulldown resistance	Termination of hiccup timer	24	36	55	Ω
V_{RES}	RES hiccup threshold		0.90	1	1.04	V
	RES upper counter threshold		3.91	4	4.07	V
	RES lower counter threshold		1.95	2	2.04	V
$I_{RES-SRC1}$	Charge current source1	V_{RES} < 1 V, CBC active	12	15	18	µA
$I_{RES-SRC2}$	Charge current source2	1 V < V_{RES}< 4 V	25	30	36	µA
$I_{RES-DIS1}$	Discharge current source1	CBC not active	3.2	5	5.5	µA
$I_{RES-DIS2}$	Discharge current source2	2 V < V_{RES} < 4 V	2.5	5	7.5	µA
HICCUP MODE BLANKING						
HC_BLK_TH	SSSR threshold to disable the hiccup blanking		5.26	5.5	5.66	V
VOLTAGE FEED-FORWARD (RAMP PIN)						
	RAMP sink impednace (clocked)		3.9	6.0	9.1	Ω
OSCILLATOR (RT PIN)						
f_{SW1}	Frequency (half oscillator frequency)	R_T = 25 kΩ	185	200	215	kHz
f_{SW2}	Frequency (half oscillator frequency)	R_T = 10 kΩ	420	480	540	kHz
	DC level		1.85	2	2.06	V
	RT sync threshold		2.8	3	3.3	V
SYNCHRONOUS RECTIFIER TIMING CONTROL (RD1 and RD2 PINS)						
t_1	SR trailing edge delay SR turn-off to primary switch turn-on	RD_1 = 20 kΩ	94	123	157	ns
		RD_1 = 100 kΩ	213	278	350	ns

(1) Guaranteed By Design

Electrical Characteristics (continued)

MIN and MAX limits apply the junction temperature range of –40°C to 125°C. Unless otherwise specified, the following conditions apply: V_{IN} = 48 V, R_T = 25 kΩ, RD_1 = RD_2 = 20 kΩ, R_{ON} =100 kΩ. No load on LSG, HSG, SR1, SR2, UVLO = 2.5 V, ON_OFF = 0 V.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_2	SR leading edge delay primary switch turn-off to SR turn-on	RD_2 = 20 kΩ	60	79	102	ns
		RD_2 = 100 kΩ	188	250	315	ns
t_{clk}	Pulse width of the clock		47	65	87	ns
COMP PIN						
V_{PWM-OS}	COMP current to RAMP offset	RAMP = 0 V	596	800	1063	µA
V_{SS-OS}	SS to RAMP offset	RAMP = 0 V	0.86	1	1.15	V
	COMP current to RAMP gain	delta RAMP/delta I_{COMP}	1895	2400	2936	Ω
	SS to RAMP gain	delta SS/delta RAMP	0.574	0.646	0.74	
	COMP current for SSSR charge curent enable	SS > 2 V	600	750	900	µA
	COMP to gate driver output delay		100	120	150	ns
	Minimum duty cycle	I_{COMP} = 1 mA			0	%
BOOST (BST PIN)						
$V_{BST(UV)}$	BST under-voltage threshold	V_{BST} - V_{SW} rising	3.2	4.137	5.6	V
	Hysteresis		0.37	0.481	0.65	V
LSG, HSG GATE DRIVERS						
V_{OL_PRI}	Low-state output voltage	$I_{HSG/LSG}$ = 100 mA	0.1	0.3	0.41	V
V_{OH_PRI}	High-state output voltage	$I_{HSG/LSG}$ = 100 mA, V_{OHL_PRI} = V_{CC} - V_{LSG}, V_{OHH_PRI} = V_{BST} - V_{HSG}	0	0.38	1	V
	Rise Time	C-load =1000 pF	2	8	12	ns
	Fall Time	C-load =1000 pF	2	10	14	ns
I_{SO_PRI}	Peak Source Current	$V_{HSG/LSG}$ = 0V		1.5		A
I_{SI_PRI}	Peak Sink Current	$V_{HSG/LSG}$ = VCC		2		A
SR1, SR2 GATE DRIVERS						
V_{OL_SR}	Low-state output voltage	$I_{SR1/SR2}$ = 10 mA			0.12	V
V_{OH_SR}	High-state output voltage	$I_{SR1/SR2}$ = 10 mA, V_{OH_SR} = V_{REF} - V_{SR}			0.313	V
	Rise Time	C-load = 1000 pF	25	45	65	ns
	Fall Time	C-load = 1000 pF	4	10	16	ns
I_{SO_SR}	Peak Source Current	V_{SR} = 0 V	0.05	0.09	0.14	A
I_{SI_SR}	Peak Sink Current	V_{SR} = V_{REF}	0.1	0.2	0.4	A
HALF BRIDGE THERMAL SHUTDOWN						
T_{SD}	Thermal Shutdown Temp			150		ºC
	Thermal Shutdown Hysteresis			25		ºC
AUX SUPPLY SWITCH CHARACTERISTICS						
	Buck Switch $R_{DS(ON)}$	I_{TEST}= 60 mA	3.0	5.2	7.5	Ω
	Synchronous Switch $R_{DS(ON)}$	I_{TEST}= 60 mA	1.2	2.8	4.5	Ω
AUX SUPPLY UNDERVOLTAGE LOCKOUT						
$V_{BST\_AUX(UV)}$	BST_AUX undervoltage threshold	V_{BST_AUX} - V_{SW_AUX} rising	2.1	2.8	3.6	V
V_{AUX_UVLO}	AUX supply UVLO input voltage rising threshold		12.2	15	16.0	V
	AUX supply UVLO input voltage falling threshold		7.9	11.2	12.7	V
AUX SUPPLY REGULATION						
$V_{AUX-OFF}$	OFF-State AUX Voltage Regulation Level		1.26	1.4	1.53	V

Electrical Characteristics (continued)

MIN and MAX limits apply the junction temperature range of –40°C to 125°C. Unless otherwise specified, the following conditions apply: V_{IN} = 48 V, R_T = 25 kΩ, RD_1 = RD_2 = 20 kΩ, R_{ON} =100 kΩ. No load on LSG, HSG, SR1, SR2, UVLO = 2.5 V, ON_OFF = 0 V.

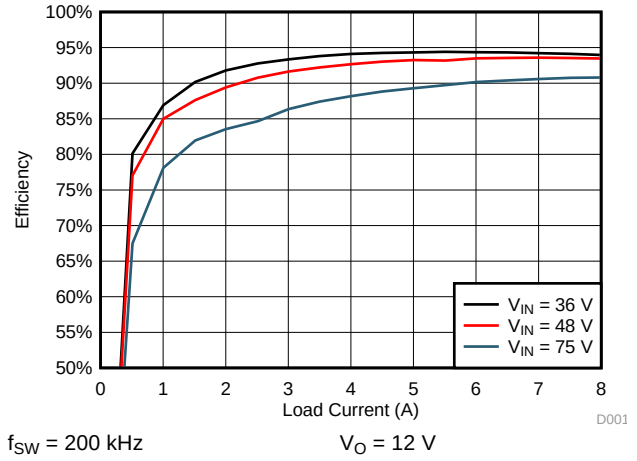
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{AUX-ON}	ON-State AUX Voltage Regulation Level		0.95	1	1.04	V
AUX SUPPLY CURRENT LIMIT						
$I_{AUX(LIM)}$	AUX Supply Current Limit Threshold		150	200	250	mA
t_{CSBLKA}	Current limit comparator blanking period measured from start of t_{ON} period (1)			50		ns
AUX SUPPLY THERMAL SHUTDOWN						
T_{SD_AUX}	AUX Supply Thermal Shutdown Temp			160		ºC
	AUX Supply Thermal Shutdown Hysteresis			28		ºC

6.6 Switching Characteristics

MIN and MAX limits apply the junction temperature range of –40°C to 125°C. Unless otherwise specified, the following conditions apply: V_{IN} = 48 V, R_T = 25 kΩ, RD_1 = RD_2 = 20 kΩ, R_{ON} =100 kΩ. No load on LSG, HSG, SR1, SR2, UVLO = 2.5 V, ON_OFF = 0 V.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{ON}	AUX SUPPLY ON-TIME	V_{IN} = 32 V, R_{ON} = 100 kΩ	240	330	440	ns
$t_{OFF(MIN)}$	AUX SUPPLY MINIMUM OFF-TIME	FB_AUX = 0 V	69	103	136	ns

6.7 Typical Characteristics



f_{SW} = 200 kHz V_O = 12 V

Figure 1. Application Board Efficiency vs Load Current

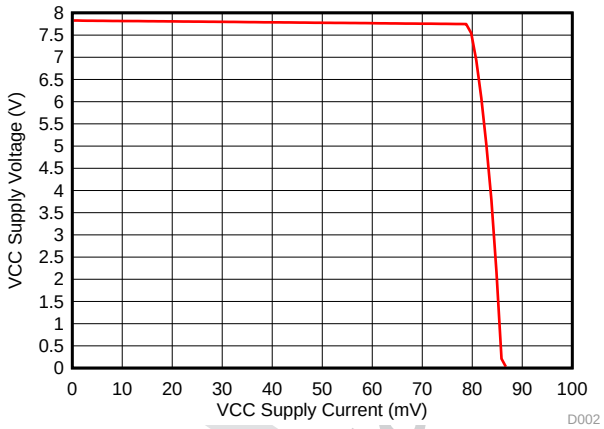


Figure 2. VCC Load Regulation

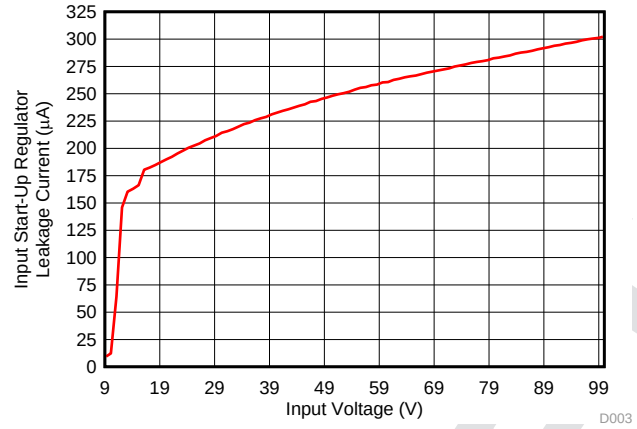


Figure 3. Input Leakage Current of Start-up Regulator vs Input Voltage

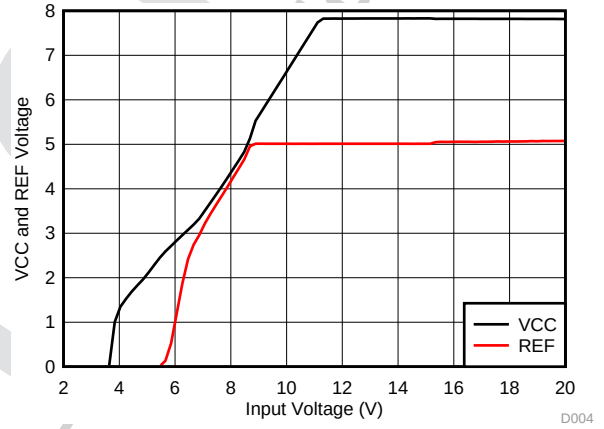


Figure 4. VCC and REF Voltage vs Input Voltage

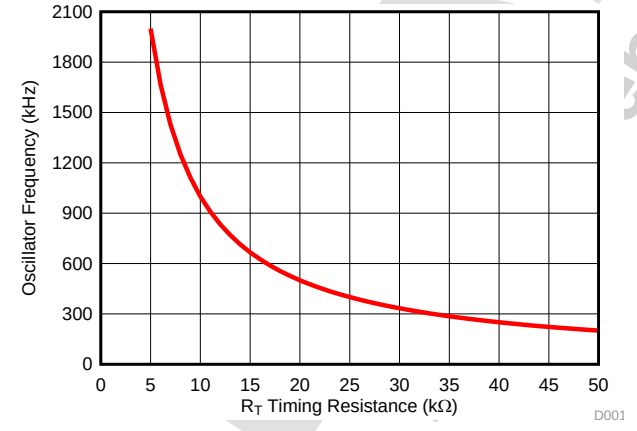


Figure 5. Oscillator Frequency vs R_T Timing Resistance

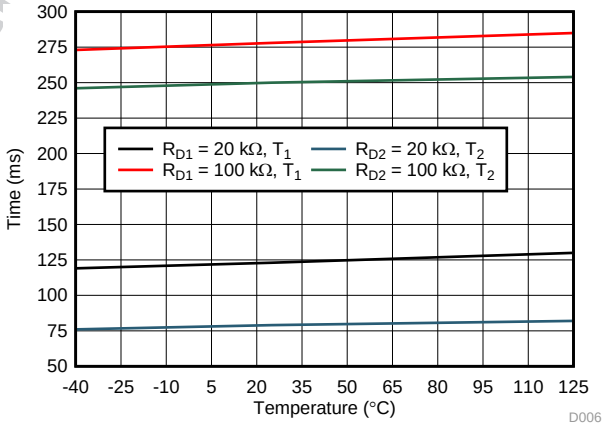


Figure 6. Dead Time vs Temperature

Typical Characteristics (continued)

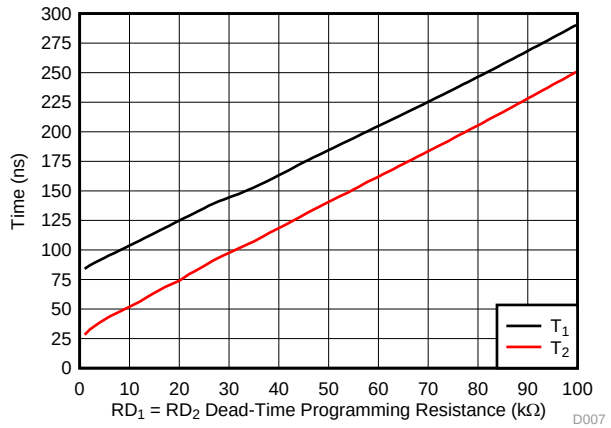


Figure 7. Dead Time vs Programming Resistance

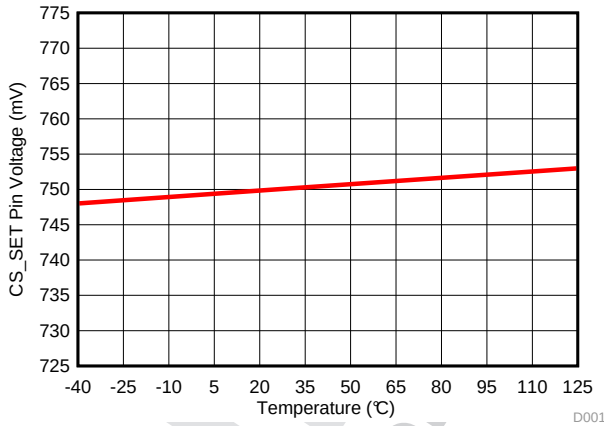


Figure 8. CS_SET Pin Voltage vs Temperature

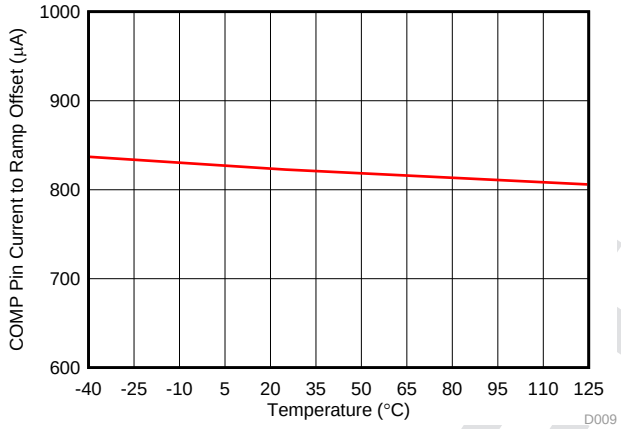


Figure 9. COMP Pin to 1-V RAMP Offset vs Temperature

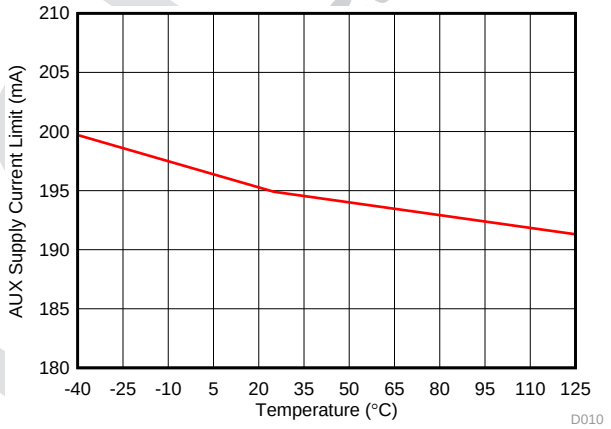


Figure 10. Auxiliary Supply Current Limit vs Temperature

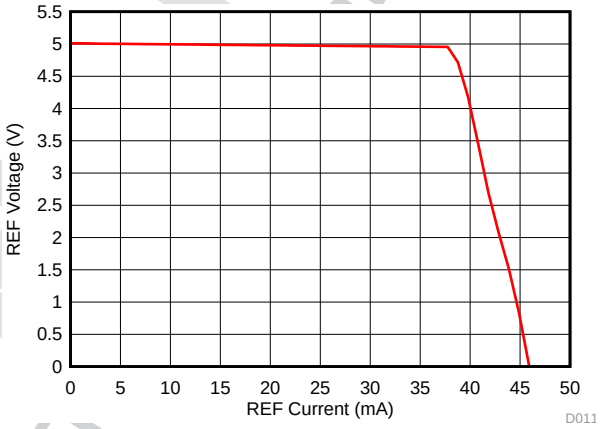


Figure 11. REF Load Regulation

7 Detailed Description

7.1 Overview

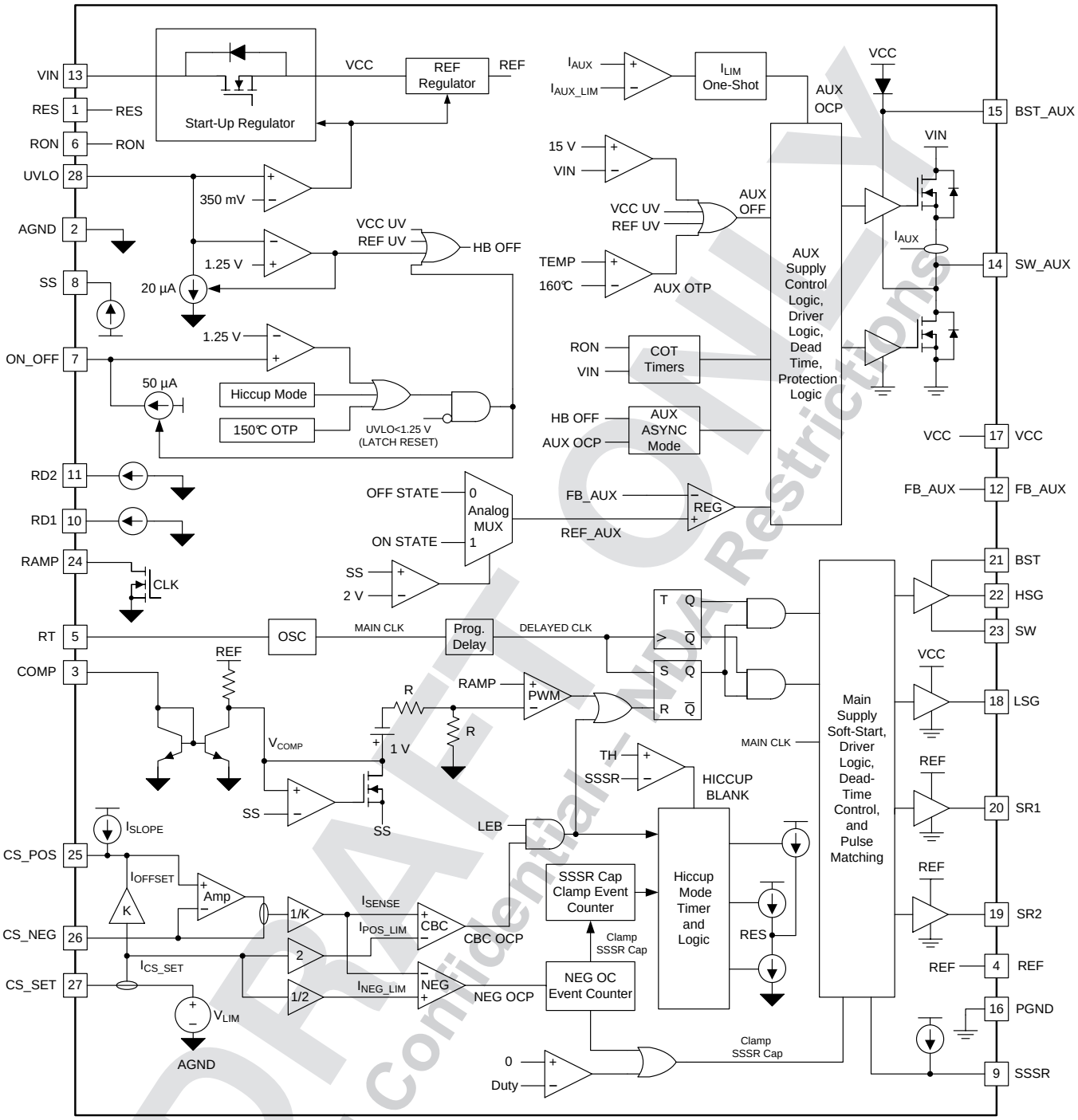
The LM5036 device is a highly-integrated, half-bridge PWM controller with integrated auxiliary bias supply. It provides a high power-density solution for telecom, datacom and industrial power converters. The device has all of the features necessary to implement a power converter that uses half-bridge topology. The device employs voltage-mode control and includes input voltage feed-forward to improve performance. This device operates on the primary side of an isolated DC-DC power converter with input voltage up to 100 V.

The soft-start function provides a fully regulated and monotonic rise of output voltage, even when the converter energizes into a pre-biased load. The device uses an enhanced cycle-by-cycle (CBC) current limit. This function matches the pulse to maintain the voltage balance of the half-bridge capacitor divider. This method ensures flux balance of the transformer during CBC operation. The input voltage compensation function helps to minimize the variation of the current limit level across the entire input voltage range.

The LM5036 device has these other features:

- configurable latch protection
- configurable overvoltage protection (OVP)
- optimized maximum duty cycle operation for the primary MOSFETs
- integrated half-bridge MOSFET gate drivers
- programmable dead-time between the primary MOSFETs and synchronous rectifiers
- auxiliary supply synchronous and asynchronous mode transition
- 5-V synchronous rectifier PWM outputs
- programmable line undervoltage lockout (UVLO)
- hiccup mode overcurrent protection (OCP)
- reverse current protection
- a 2-MHz capable oscillator with synchronization capability
- two-level thermal shutdown protection

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 High-Voltage Start-Up Regulator

The LM5036 device contains a high-voltage VCC start-up regulator that allows the input pin (VIN) to be connected directly to an input voltage up to 100 V. When the UVLO pin voltage is greater than 0.35 V, the start-up regulator is enabled to charge an external capacitor connected to the VCC pin. The output voltage of the VCC regulator is regulated at 7.8 V (typical). The VCC regulator provides power to the reference (REF) regulator. The regulator output at VCC is internally current limited to 81 mA (typical) . The value of the VCC capacitor depends on the total system design, and its start-up characteristics. The recommended range of values for the VCC capacitor is 0.47 µF to 10 µF.

LM5036 can power itself using its internal high-voltage start-up linear regulator, but internal power dissipation can be reduced by powering VCC from an auxiliary switched mode supply. LM5036 device integrates all of the functions needed to implement a low-cost and easy-to-design isolated fly-buck auxiliary supply based on the constant-on-time (COT) control scheme. The primary output V_{AUX1} of the auxiliary supply must be connected through a diode to the VCC pin, as shown in Figure 12. The auxiliary supply must raise the VCC voltage above the internally generated VCC voltage in order to shut off the internal start-up regulator. Powering VCC from an auxiliary switched mode supply improves efficiency while reducing the power dissipation of the controller IC. The VCC under-voltage (UV) circuit will still function in this mode, requiring that VCC never falls below its UV threshold during the start-up sequence. The VCC regulator series pass transistor includes a diode between VCC and VIN that should not be forward biased in normal operation. Therefore, the auxiliary VCC voltage should never exceed the VIN voltage.

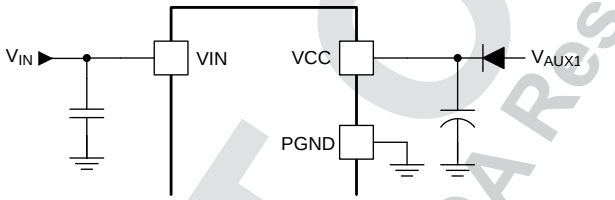


Figure 12. External VCC Bias Supply Connection

7.3.2 Undervoltage Lockout (UVLO)

The LM5036 device contains a three-level under-voltage lockout circuit. When the UVLO pin voltage is below 0.35 V, the controller is in a low current shutdown mode where the functional circuit blocks are not enabled including VCC startup regulator, auxiliary supply and the main half-bridge control logic and gate drive circuitry, etc.

When UVLO pin voltage is above 0.35 V, the VCC and REF regulators become active.

When the VCC and REF outputs exceed their respective UV thresholds and the input voltage VIN is above 15 V, the auxiliary supply is enabled.

When UVLO pin voltage is above 1.25 V and VCC and REF voltage are above their respective UV thresholds, the control logic of the main half-bridge converter is enabled. The soft-start capacitor is released and the normal operation begins. An external set-point voltage divider from VIN to GND can be used to set the minimum operating voltage of the half-bridge converter. The divider must be designed such that the voltage at the UVLO pin is greater than 1.25 V when VIN enters the desired operating range. UVLO hysteresis is accomplished with an internal 20-µA current sink that is switched on or off into the impedance of the external set-point divider. When the UVLO threshold of 1.25 V is exceeded, the current sink is deactivated to quickly raise the voltage at the UVLO pin. When the UVLO pin voltage falls below the 1.25-V threshold, the current sink is enabled causing the voltage at the UVLO pin to quickly fall.

7.3.3 Reference Regulator

The REF pin is the output of a 5-V linear regulator that can be used to bias an opto-coupler transistor, primary side of an isolated gate driver or digital isolator, among other housekeeping circuits. The regulator output is internally current limited to 39 mA (typical). The REF pin must be locally decoupled with a ceramic capacitor, the recommended range of values is from 0.1 µF to 10 µF.

7.3.4 Oscillator, Synchronized Input

The oscillator frequency of LM5036 device is set by a resistor connected between the RT pin and AGND. The R_T resistor should be located close to the device. To set a desired oscillator frequency (f_{OSC}), the value of R_T resistor can be calculated from Equation 1.

$$R_T = \frac{1}{f_{OSC} \times 1 \times 10^{-10}} \quad (1)$$

For example, if the desired oscillator frequency is 400 kHz, that is, each phase (LSG and HSG) switches at 200 kHz, the value of R_T is calculated to be 25 kΩ. If the LM5036 device is to be synchronized to an external clock, that signal must be coupled into the RT pin through a 100 pF capacitor. The RT pin voltage is nominally regulated at 2 V and the external pulse amplitude should lift the pin to between 3.5 V and 5.0 V on the low-to-high transition. The synchronization pulse width should be between 15 and 200 ns. The RT resistor is always required, whether the oscillator is free running or externally synchronized and SYNC frequency must be equal to or greater than the frequency set by the R_T resistor.

7.3.5 Voltage-Mode Control

The LM5036 device employs voltage-mode control with input voltage feed-forward for the main half-bridge converter. A simplified block diagram of the voltage-mode feedback control loop is shown in Figure 13.

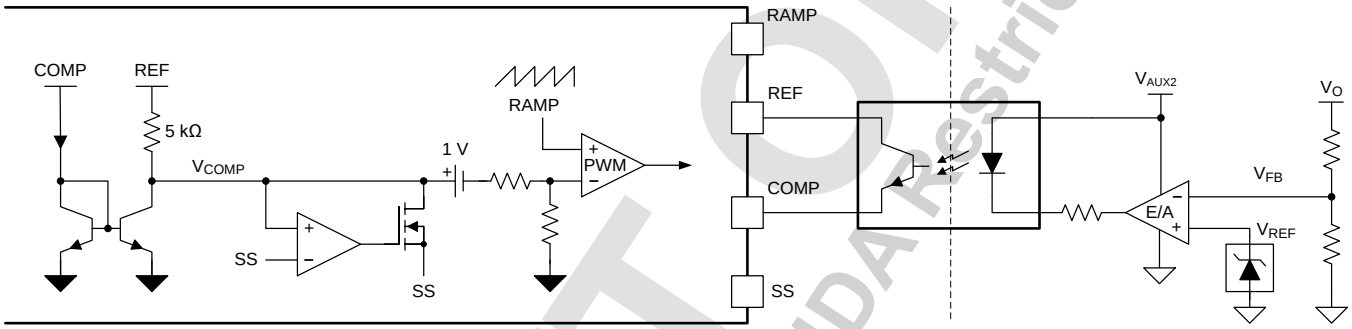


Figure 13. Voltage-Mode Feedback Control Loop for Half-Bridge Converter

The output voltage (V_O) is sensed and compared against a reference voltage (V_{REF}) on the secondary side which produces an error voltage which is then processed by the error amplifier. The compensated error signal is transmitted across the isolation boundary through an opto-coupler and then gets injected into the COMP pin in the form of a control current. The COMP pin current is internally mirrored by a matching pair of NPN transistors which sink current through a 5-kΩ resistor connected to the 5-V internal reference. The resulting control voltage V_{COMP} is compared with the soft-start capacitor voltage (SS) and the smaller of the two passes through a 1-V offset, followed by a 2:1 resistor divider before being applied to the PWM comparator to determine the duty cycle of the half-bridge converter. The PWM comparator polarity is configured such that with no current flowing into the COMP pin, the controller produces maximum duty cycle for the primary FETs.

An opto-coupler detector can be connected between the REF pin and the COMP pin. Because the COMP pin is controlled by a current input, the voltage across the opto-coupler detector is nearly constant. The bandwidth limiting phase delay which is normally introduced by the significant capacitance of the opto-coupler is thereby greatly reduced. Higher loop bandwidths can be realized because the bandwidth limiting pole associated with the opto-coupler is now at a much higher frequency.

The voltage at the RAMP pin provides the modulation ramp for the PWM comparator. The PWM comparator compares the modulation ramp signal at the RAMP pin to the COMP voltage to control the duty cycle. The modulation ramp signal can be implemented as a ramp proportional to the input voltage, known as feed-forward voltage mode control, as shown in Figure 14. The RAMP pin is reset by an internal MOSFET when RAMP voltage passes COMP voltage, current limit event, or at the conclusion of each PWM cycle, whichever comes earlier.

(1) Slope proportional to input voltage (see Figure 15)

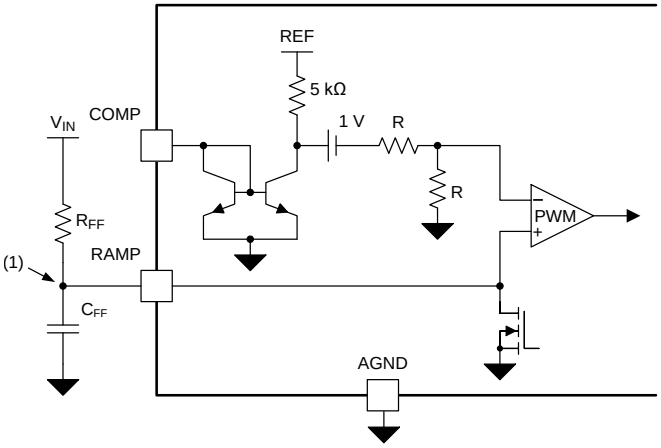


Figure 14. Feed-Forward Voltage-Mode Control Configuration

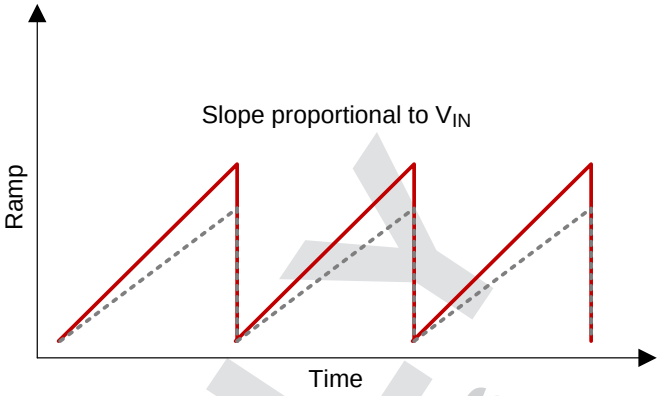


Figure 15. Modulation Ramp Slope

An external resistor (R_{FF}) and capacitor (C_{FF}) connected to VIN, AGND, and the RAMP pins are required to create a saw-tooth modulation ramp signal. The slope of the signal at RAMP will vary in proportion to the input voltage. The varying slope provides line feed-forward information necessary to improve line transient response with voltage-mode control. With a constant control signal, the on-time (T_{ON}) varies inversely with the input voltage (V_{IN}) to stabilize the volt-second product of the transformer. Using a line feed-forward ramp for PWM control requires very little change in the voltage regulation loop to compensate for changes in input voltage, as compared to a ramp with fixed slope. In addition, voltage-mode control is less susceptible to noise. Therefore, it is a good choice for wide input range power converter applications. However, voltage-mode control requires a Type-III compensation network due to the complex-conjugate poles of the L-C output filter.

The recommended capacitor value range for C_{FF} is from 100 pF to 1800 pF. Referring to Figure 14, it can be seen that C_{FF} value must be small enough to be discharged within the clock pulse-width. The value of R_{FF} required can be calculated from Equation 2

$$R_{FF} = \frac{-1}{f_{OSC} \times C_{FF} \times \ln\left(1 - \frac{V_{RAMP}}{V_{IN(min)}}\right)} \quad (2)$$

For example, assuming a V_{RAMP} voltage of 1.5 V (a good compromise of signal range and noise immunity), $V_{IN(min)}$ of 36 V, oscillator frequency of 400 kHz and C_{FF} = 560 pF results in R_{FF} = 105 kΩ.

7.3.6 Primary-Side Gate Driver Outputs (LSG and HSG)

The LM5036 device provides two gate driver outputs for the primary FETs of the main half-bridge converter: one floating high-side gate driver output HSG and one ground referenced low-side gate driver output LSG. Each internal gate driver is capable of sourcing 1.5-A peak and sinking 2-A peak (typical). Initially, the LSG output is turned on during the power transfer phase, followed by a freewheeling period during which both LSG and HSG outputs are turned off. In the subsequent power transfer phase, the HSG output is turned on followed by another freewheeling period.

The low-side LSG gate driver is powered directly by the VCC bias supply. The HSG gate driver is powered from a bootstrap capacitor connected between BST and SW. An external diode connected between VCC and BST provides the high-side gate driver power by charging the bootstrap capacitor from VCC when the switching node SW is low. When the high side FET is turned on, BST rises to a peak voltage equal to VCC + VIN.

The BST and VCC capacitors should be placed close to the pins of the LM5036 device to minimize voltage transients due to parasitic inductance because the peak current source to the MOSFET gates can exceed 1.5 A (typical). The recommended value of the BST capacitor is 0.1 µF or greater. A low ESR/ESL capacitor, such as a surface mount ceramic, should be used to prevent voltage drop during the HSG transitions.

7.3.7 Half-Bridge PWM Scheme

Synchronous rectification on the secondary side of the transformer provides higher efficiency, especially for low output voltage and high output current converter, compared to the diode rectification. The reduction of the diode forward voltage drop (0.5 V to 1.5 V) to 10 mV to 200 mV V_{DS} voltage for a MOSFET significantly reduces rectification losses. In a typical application, the secondary windings of the transformer can be center tapped, with the output power inductor in series with the center tap, as shown in Figure 16. The synchronous rectifiers (SRs) provide the ground path for the energized secondary winding and the inductor current.

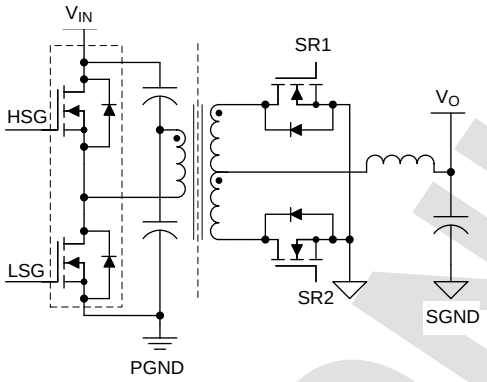


Figure 16. Half-bridge Topology with Center-Tap Rectification

The internal SR drivers are powered by the REF regulator and each SR output is capable of sourcing 0.1 A and sinking 0.2 A peak (typical). The amplitude of the SR drivers is limited to 5 V. The 5-V SR signals enable the transfer of SR control signals across the isolation barrier either through a digital isolator or isolated gate driver. It should be noted that the actual gate sourcing and sinking currents for the SRs are provided by the secondary-side gate drivers.

The timing diagram of the four PMW signals (LSG, HSG, SR1, and SR2) with dead-times is illustrated in Figure 17. The main clock is generated by the internal oscillator. A delayed clock is derived by adding a delay of t_D to the main clock. t_D can be calculated from Equation 3, where RD_1 is the value of the resistor connected between RD1 pin and AGND.

$$t_D = RD_1 \times 2\,pF + 20\,ns \quad (3)$$

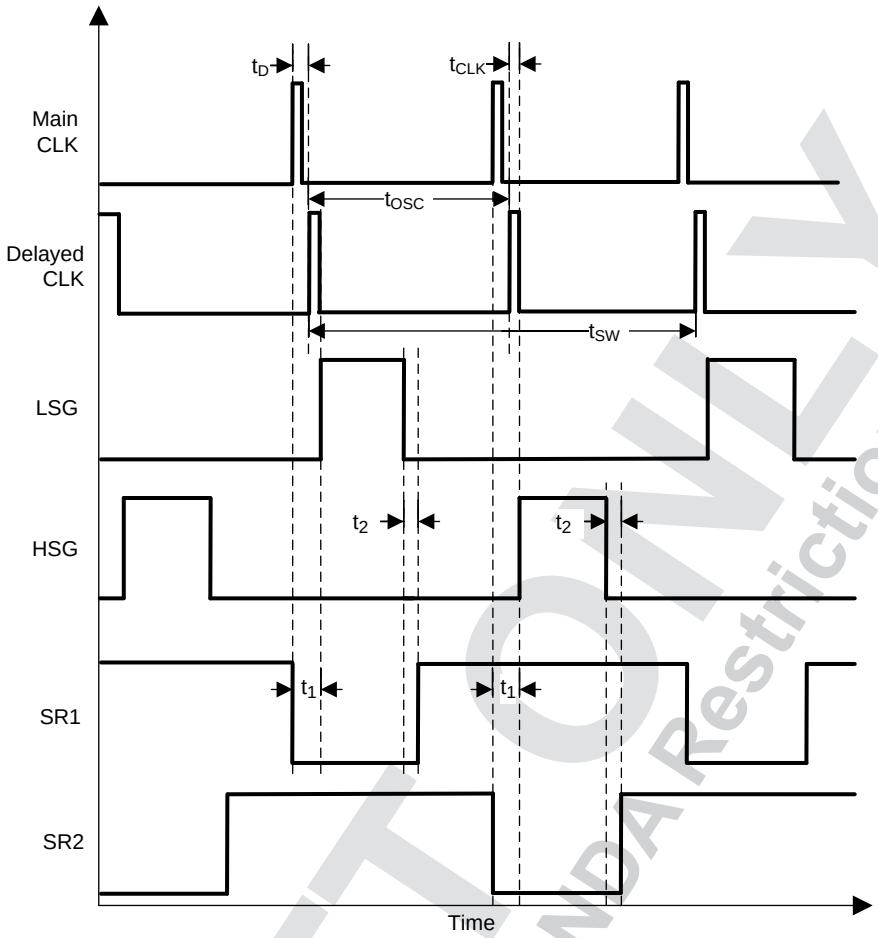


Figure 17. PWM Signal Timing Diagram

As illustrated in Figure 17, the rising edge of the main clock is used to turn off the SRs. Primary FET drive signal LSG/HSG is turned on at the falling edge of the delayed clock. Therefore, the dead-time between the falling edge of SR and the rising edge of the respective primary FET can be calculated from Equation 4

$$t_1 = t_D + t_{CLK} \quad (4)$$

where

- t_{CLK} is the pulse width of the clock which is 65 ns (typical).

The minimum achievable t_1 is equal to the pulse width of the clock when t_D is set to 0 ns.

After SR1 is turned off, the body diode of SR1 continues to carry about half the inductor current until the primary power raises the drain voltage of the SR1 and reverse biases its body diode. Ideally, dead-time t_1 would be set to the minimum time that allows the SR to turn off before the body diode starts conducting.

Power is transferred from the primary to the secondary side when the LSG is turned on. During this power transfer period, the SR2 is still turned on while the SR1 is turned off. The drain voltage of SR1 is twice the voltage of the center tap at this time. Under the normal operation, the LSG is turned off either when the RAMP signal exceeds the COMP signal or at the rising edge of the next delayed clock signal (maximum duty cycle condition), whichever comes earlier. A dead-time t_2 is inserted between the falling edge of LSG and rising edge of SR1. t_2 can be calculated from Equation 5, where RD_2 is the value of the resistor connected between RD2 pin and AGND.

$$t_2 = RD_2 \times 2\ pF + 30\ ns \quad (5)$$

During the dead-time t_2, the inductor current continues to flow through the body diode of SR1. Because the body diode causes more conduction loss than the SR, efficiency can be improved by minimizing the t_2 period while maintaining sufficient margin across the entire operating conditions (component tolerances, input voltages, etc.) to prevent the cross conduction between the primary FET and SR.

During the freewheeling period where both of the primary FETs are turned off while both of the SRs are turned on, the inductor current is almost equally shared between SR1 and SR2 which effectively shorts the secondary winding of the transformer. SR2 is then turned off before HSG is turned on. The power is transferred from the primary to secondary side again when HSG is turned on. After HSG is disabled and the dead-time t_2 expires, SR1 and SR2 both conduct again during the freewheeling period.

7.3.8 Maximum Duty Cycle Operation

The LSG and HSG will operate at maximum duty cycle when they are turned off at the rising edge of the delayed clock, instead of by the event where RAMP voltage passes COMP voltage, as shown in Figure 18. In LM5036 device, it is intended to achieve optimized maximum duty cycle for the primary FETs in order to accommodate wider range of operation.

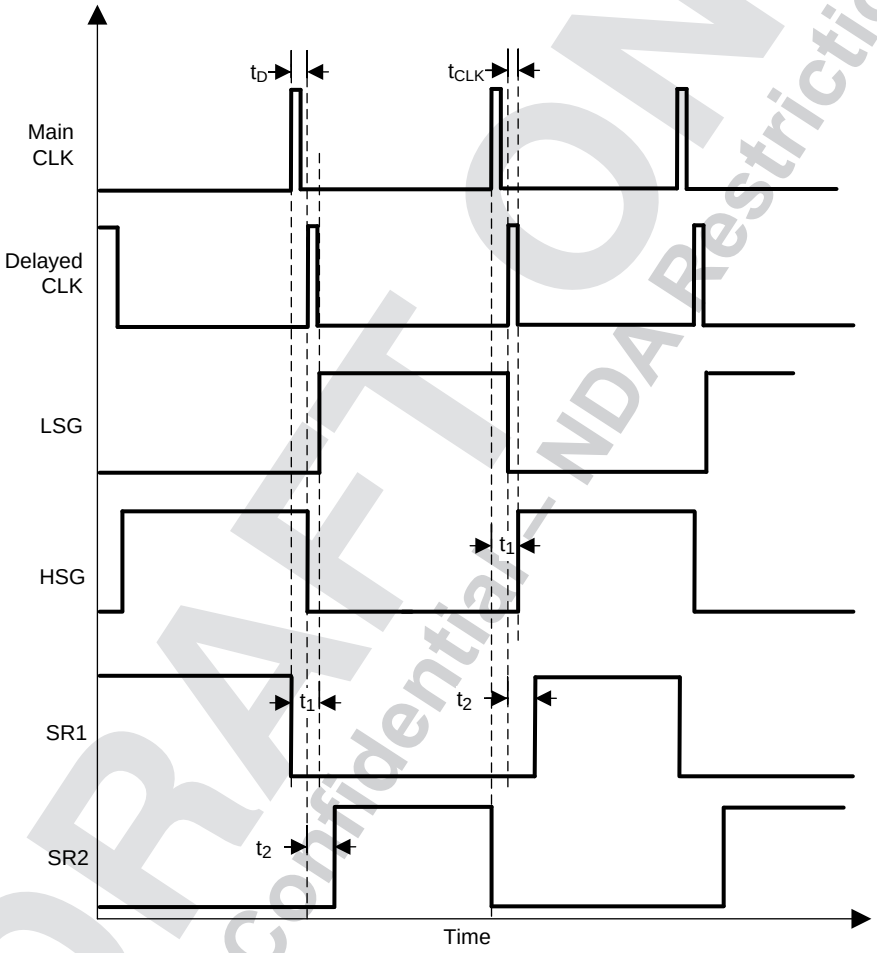


Figure 18. PWM Signals at Maximum Duty Cycle Condition

Use Equation 6 to calculate the maximum duty cycle for the primary FETs

$$D_{MAX} = \frac{\frac{1}{f_{OSC}} - t_{CLK}}{\frac{2}{f_{OSC}}} \quad (6)$$

where

- f_{OSC} is the oscillator frequency which is twice the switching frequency

The pulse width of the clock is used in this case to prevent cross-conduction between the two primary FETs during the maximum duty cycle operation.

7.3.9 Pre-Biased Start-Up Process

The soft-start functionality limits the inrush current and voltage stress of the power converter. A common requirement for the power converters used in the telecom/datacom applications is to have a monotonic output voltage start-up into pre-biased load conditions where the output capacitor is pre-charged prior to start-up. In a pre-biased load condition, if the synchronous rectifiers are engaged prematurely they will sink current from the pre-charged output capacitors resulting in undesired output voltage dip or even power converter damage. The LM5036 device implements unique circuitry to ensure intelligent turn-on of the synchronous rectifiers such that the output voltage has monotonic start-up.

The start-up process can be divided into two phases:

- soft-start of the primary FETs
- soft-start of the SRs

7.3.9.1 Primary FETs Soft-Start Process

Figure 19 shows a simplified block diagram of the soft-start function.

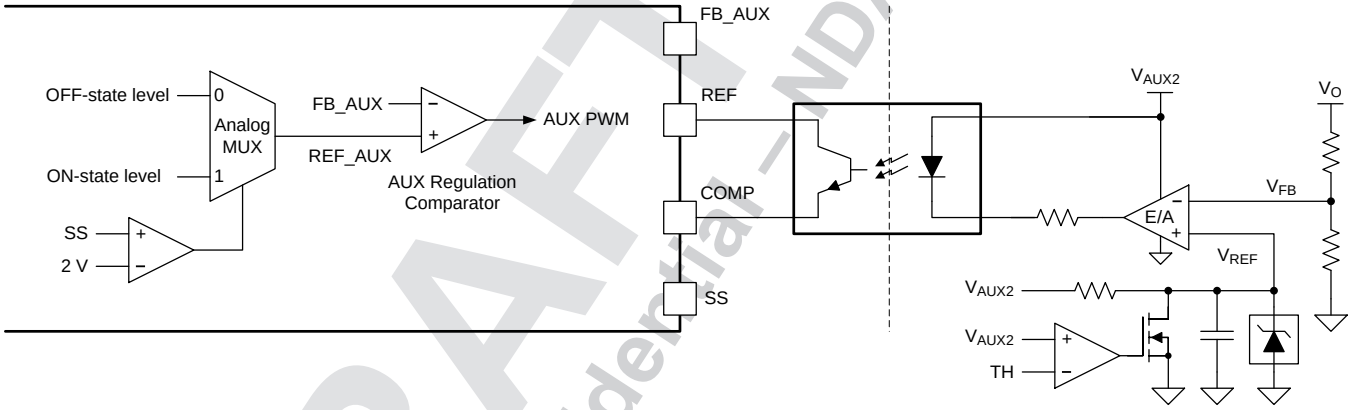


Figure 19. Soft-Start Function

The auxiliary supply has two reference output voltage levels of 1.4 V (off state) and 1 V (on state) which facilitates easy voltage level shift detection on the secondary side. The auxiliary supply starts to operate as soon as VIN > 15 V (typical) and VCC and REF are above the respective UV thresholds. When the soft-start capacitor is below 2 V, the auxiliary supply will produce the off-state voltage on the primary (V_{AUX1}) and secondary side (V_{AUX2}), as shown in Figure 20.

The off-state auxiliary output voltage level present on the secondary side V_{AUX2} is above the threshold TH, which activates a reset circuit that discharges the output voltage reference V_{REF}. This ensures that the opto-coupler is producing a 0% duty-cycle command. When UVLO exceeds 1.25 V and VCC and REF are above the respective UV thresholds, the soft-start capacitor starts to charge. The auxiliary supply will produce the on-state voltage level when the soft-start capacitor reaches 2 V.

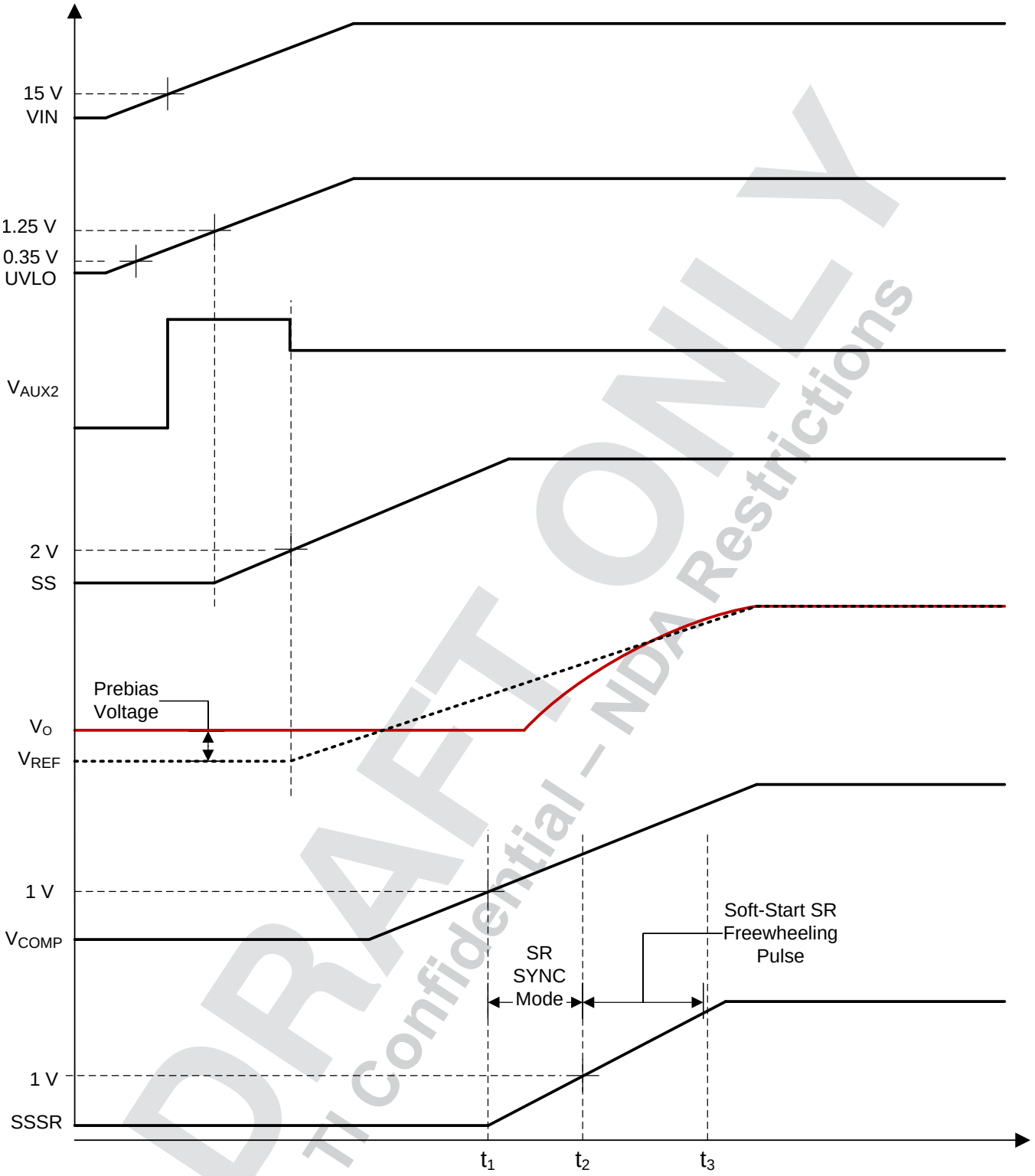


Figure 20. Pre-biased Start-Up Waveform

The secondary side reset circuit will now be disabled because V_{AUX2} < TH, and the output voltage reference is released. The reference capacitor soft-starts the output voltage under full regulation. By using the modulation of the auxiliary output voltage, the communication between the primary and secondary side is established without the need of any additional opto-coupler.

Due to the introduced programmable soft-start delay (before SS capacitor reaches 2 V), the duty cycle is controlled by the feedback control loop at all times without being interfered by the SS capacitor voltage (because $V_{COMP} < V_{SS}$). When the reference voltage exceeds the pre-bias voltage at the output, the V_{COMP} starts to rise. After V_{COMP} reaches the 1-V threshold (for example I_{COMP} = 800 µA) which corresponds to zero duty cycle, the duty cycle of the primary FETs starts to increase. In the meantime, the device starts to charge SSSR capacitor with a 20-µA current source when the duty cycle is greater than zero.

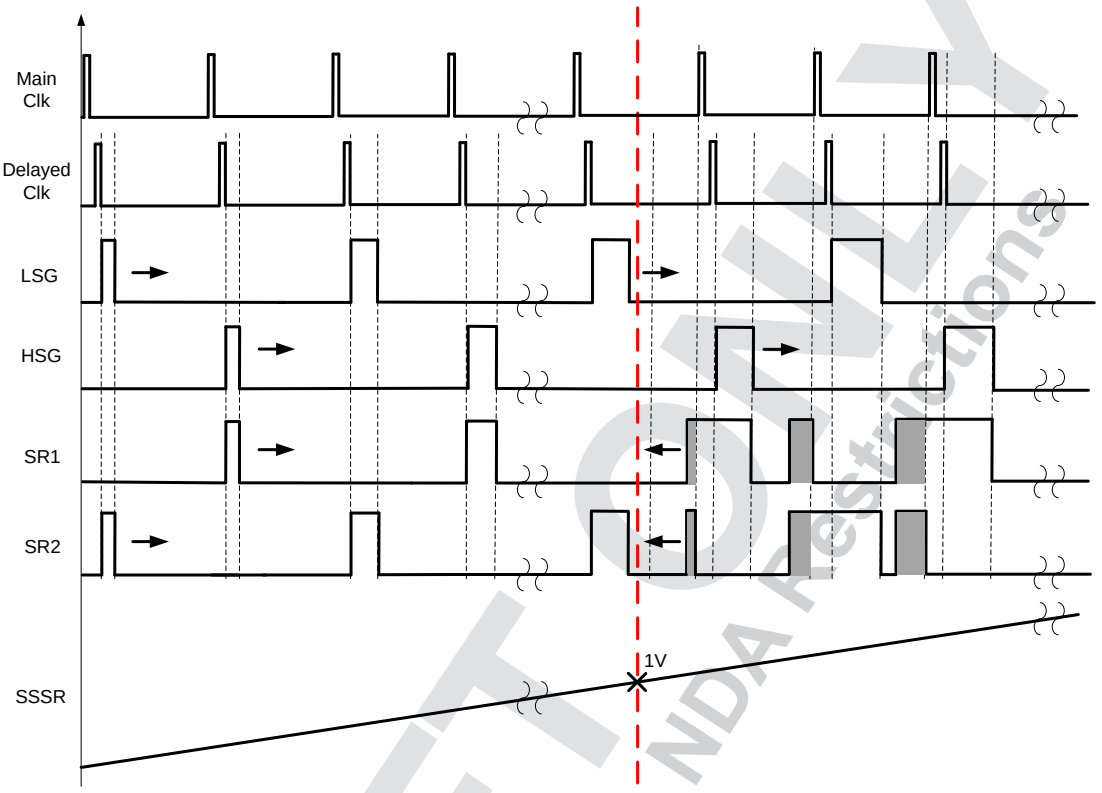


Figure 21. PWM Timing During Startup Process

7.3.9.2 Synchronous Rectifier (SR) Soft-Start Process

Until SSSR capacitor reaches 1 V, the controller operates at SR synchronization (SYNC) mode where the SR pulses are synchronized to the respective primary FET pulses, as shown in Figure 21. This helps to reduce the conduction loss of the SRs. In addition, due to the fact that the SRs only conduct during power transfer phase, there is no risk of reverse current at the SYNC mode. Since the pulse width of SRs gradually increases, the output voltage disturbance due to the difference in the voltage drop between the body diode and the on resistance of the SRs is prevented.

Once the SSSR capacitor crosses the 1-V threshold, the LM5036 device begins the soft-start of the SRs freewheeling period (highlighted in gray in Figure 21) where the SRs may sink current from the output if they are engaged prematurely. The 1-V offset on the SSSR pin is intended to provide additional delay which ensures that the primary duty cycle ramps up to a point where the output voltage is in-regulation, thereby avoiding reverse current when the SRs are engaged. The SR soft-start follows a leading-edge modulation technique such that the leading-edge of the SR pulse is soft-started as opposed to the trailing-edge modulation of the primary FETs. As shown in Figure 21, SR1 and SR2 are turned on simultaneously with a narrow pulse-width during the freewheeling period. At the end of the freewheel period, that is, at the rising edge of the main CLK, the SR in phase with the next power transfer cycle remains on while the SR out of phase with it is turned off. The in-phase SR remains on throughout the power transfer cycle and at the end of it, both the primary FET and the in-phase SR are turned off simultaneously. At the end of the soft-start, the SR pulses will become complementary to the respective primary FETs, as shown in Figure 17.

7.3.10 Zero Duty Cycle Operation

The zero duty cycle detection ensures that there is no excessive reverse current when the primary duty cycle is zero. In that case, the SSSR capacitor would be clamped to ground and therefore SRs will be turned off (SR SYNC mode). Normal operation will resume (SSSR capacitor start to charge) as soon as the load is applied. It should be noted about a special application scenario where there is a low output capacitance value. During the start-up under no load condition, the output capacitor acts like a load. With small output capacitor the converter might get stuck in zero duty until load is applied.

7.3.11 Enhanced Cycle-by-Cycle Current Limiting with Pulse Matching

Figure 22 illustrates the half-bridge converter with low-side current sensing using a sense resistor.

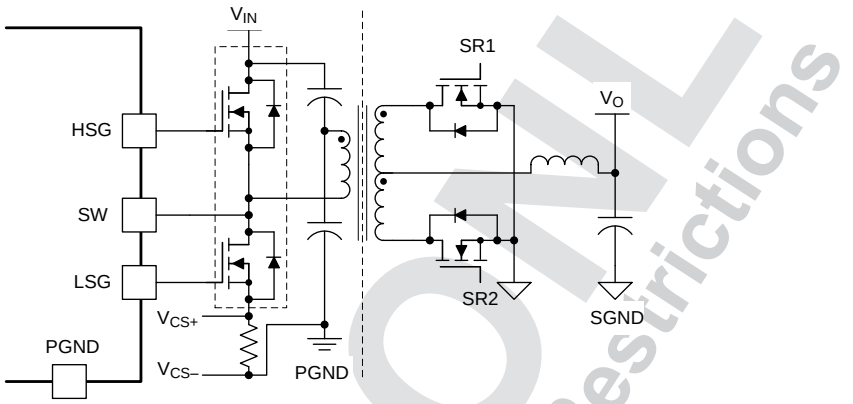


Figure 22. Half-Bridge Converter with Low-Side Current Sensing

In LM5036 device, current limiting for the half-bridge converter is accomplished with three pins, including CS_SET, CS_POS and CS_ NEG pins, as shown in Figure 23 .

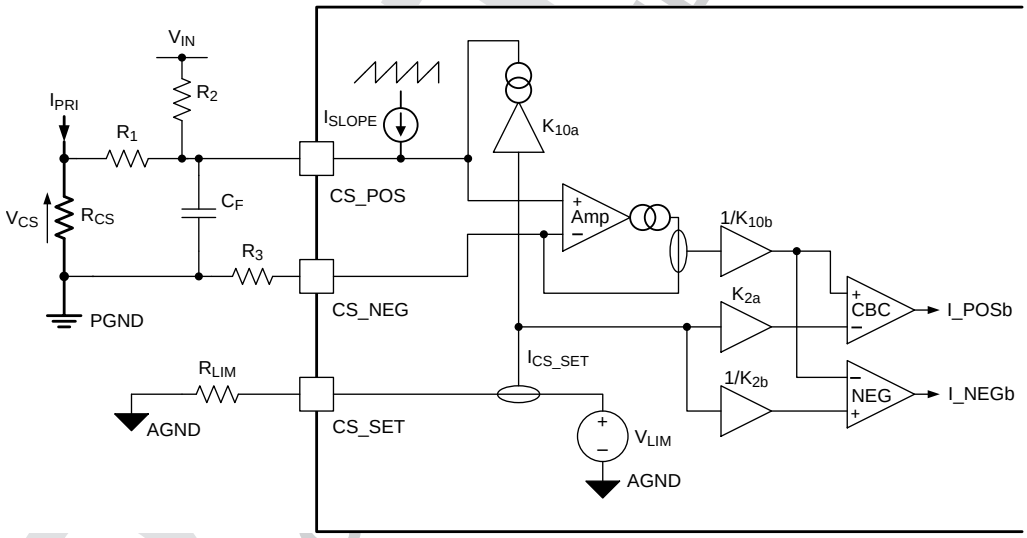


Figure 23. Block Diagram of the Current Limiting Function

CS_SET pin is used to set the internal current limit threshold with an external resistor R_{LIM} according to Equation 7.

$$I_{CS\_SET} = \frac{V_{LIM}}{R_{LIM}} \quad (7)$$

where

- V_{LIM} = 0.75 V (typical) is the internal current limit setting voltage.

The CS_POS pin is driven by a signal representative of the current flowing through the low-side FET of the half-bridge converter. The current sense voltage at CS_POS pin (equal to CS_NEG pin voltage) is converted to a current sense signal through R_3 which is then sensed, scaled and compared against the internal current limit thresholds. In order to blank the leading-edge transient noise seen when the low-side FET is turned on, the current sense signal is blanked for t_{CSBLK} after LSG is turned on. If the magnitude of the noise spike is excessive, an additional filter capacitor C_F may be added to form an RC filter with R_1 to reduce the high-frequency noise spike. Both the leading-edge blanking and RC filter help to prevent false triggering of CBC current limiting operation.

In order to achieve bi-directional current sensing, an internal offset current (K_{10a} x I_{CS_SET}), is injected to the CS_POS pin. This offset allows positive internal thresholds on the CBC and NEG comparators that correspond to effective I_{CS_SET} and $-I_{CS\_SET}$ / 2 thresholds at the input.

When the current sense signal (I_{R3} x 1 / K_{10b}) reaches the positive threshold (K_{2a} x I_{CS_SET}), CBC current limiting operation is activated. The controller essentially operates in peak current mode control, with the voltage loop open, during the CBC operation. A common issue with peak current mode control is sub-harmonic oscillation. This occurs when the effective duty cycle is greater than 50%. A common solution for sub-harmonic oscillation is to add slope compensation. The slope of the compensation ramp must be set to at least one half the downslope of the output inductor current transformed to the primary side across the current sense resistor. To eliminate sub-harmonic oscillation after one switching cycle, the slope compensation must be equal to the downslope of the output inductor current. This is known as deadbeat control. In LM5036, the slope compensation signal is a saw-tooth current signal ramping up from 0 to I_{SLOPE} at the oscillator frequency (twice the switching frequency of each primary FET).

However, another issue will arise after slope compensation is added. The current limit level varies with the input voltage, as illustrated in Figure 24. Because the slope compensation magnitude is different at different input voltages, the actual current limit level varies with input voltage for a given internal current limit threshold.

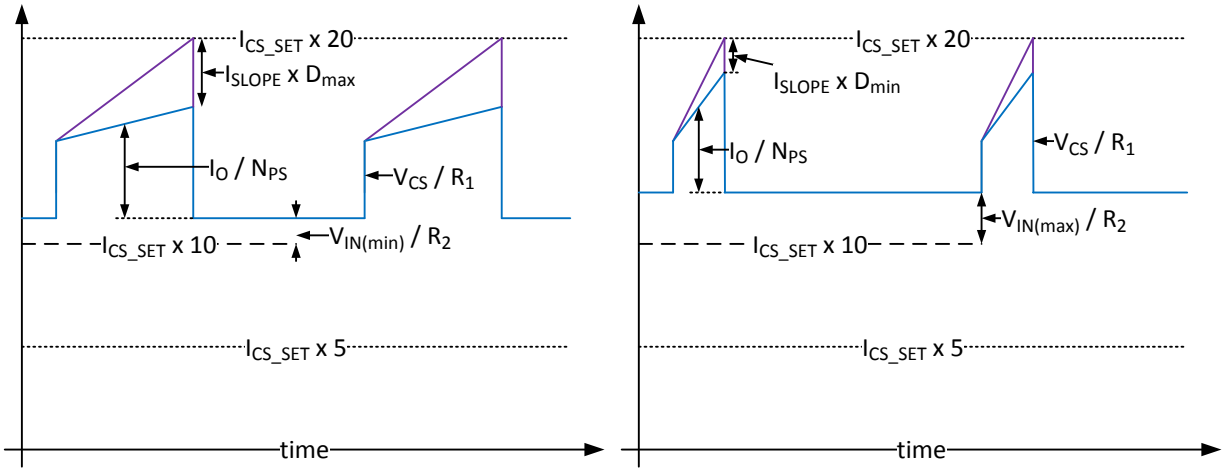


Figure 24. Current Sense and Current Limit Waveforms

A new feature, input voltage compensation, is provided by LM5036. By adding an extra signal, which is a function of input voltage, on top of the current sense signal and the slope compensation signal, variation of the current limit level can be minimized over the entire input voltage range. The CS_POS pin voltage at time t, after the rising edge of LSG, is expressed by Equation 8:

$$v_{CS\_POS}(t) = v_{CS}(t) + R_1 \times \left(I_{CS\_SET} \times K_{10a} + \frac{V_{IN} - v_{CS\_POS}(t)}{R_2} + I_{SLOPE} \times t \times f_{OSC} \right) \quad (8)$$

$$v_{CS\_POS}(t) = \frac{v_{CS}(t) + R_1 \times \left(I_{CS\_SET} \times K_{10a} + \frac{V_{IN}}{R_2} + I_{SLOPE} \times t \times f_{OSC} \right)}{1 + \frac{R_1}{R_2}} \quad (9)$$

At the trip threshold, of the CBC comparator, both its inputs are at the same potential. In this case the voltage on the CS_NEG pin is expressed by Equation 10.

$$v_{CS\_NEG} = I_{CS\_SET} \times K_{2a} \times K_{10b} \times R_3 \quad (10)$$

$$v_{CS\_POS}(t) = v_{CS\_NEG} \quad (11)$$

For a given duty cycle (D) the current sense threshold voltage that will just trigger the CBC comparator can be determined by combining Equation 9, Equation 10 and Equation 11.

$$v_{CS\_CBCTh} = R_1 \times \left(I_{CS\_SET} \times \left(K_{2a} \times K_{10b} \times R_3 \left(\frac{1}{R_1} + \frac{1}{R_2} \right) - K_{10a} \right) - \frac{V_{IN}}{R_2} - I_{SLOPE} \times D \right) \quad (12)$$

Now if we assume:

$$\frac{1}{R_3} = \frac{1}{R_1} + \frac{1}{R_2}$$

$$K_{10a} = K_{10b} = 10$$

$$K_{2a} = 2$$

$$D = t_{ON} \times f_{OSC} = \frac{2 \times V_O}{V_{IN}} \times N_{PS}$$

$$N_{PS} = \frac{N_P}{N_S} \quad (13)$$

Equation 12 simplifies to Equation 14.

$$v_{CS\_CBCTh} = R_1 \times \left(\frac{K_{CBC1}}{R_{LIM}} - \frac{V_{IN}}{R_2} - I_{SLOPE} \times \frac{2 \times V_O}{V_{IN}} \times N_{PS} \right)$$

Where

$$K_{CBC1} = V_{LIM} \times (K_{2a} \times K_{10b} - K_{10a}) \quad (14)$$

LM5036 ensures flux balance of the main transformer during CBC operation. The duty cycles of the two primary FETs are always matched. If the low-side FET is terminated due to a current limit event, a matched duty cycle will be applied to the high-side FET during the next half switching period, regardless of the current condition. The matched duty cycles ensure voltage-second balance of the transformer which prevents transformer saturation.

The pulse matching operation is illustrated in Figure 25. When the current limit is reached during the low-side phase, a FLAG signal goes high. The RAMP signal is sampled at the rising edge of the FLAG signal and then held through the next half switching period for the high-side phase. When the high-side phase RAMP signal rises above the sampled value, the high-side PWM pulse is turned off so that the duty cycle are matched for both phases. In the meantime, the hiccup restart capacitor is charged with a 15-µA current source during CBC operation.

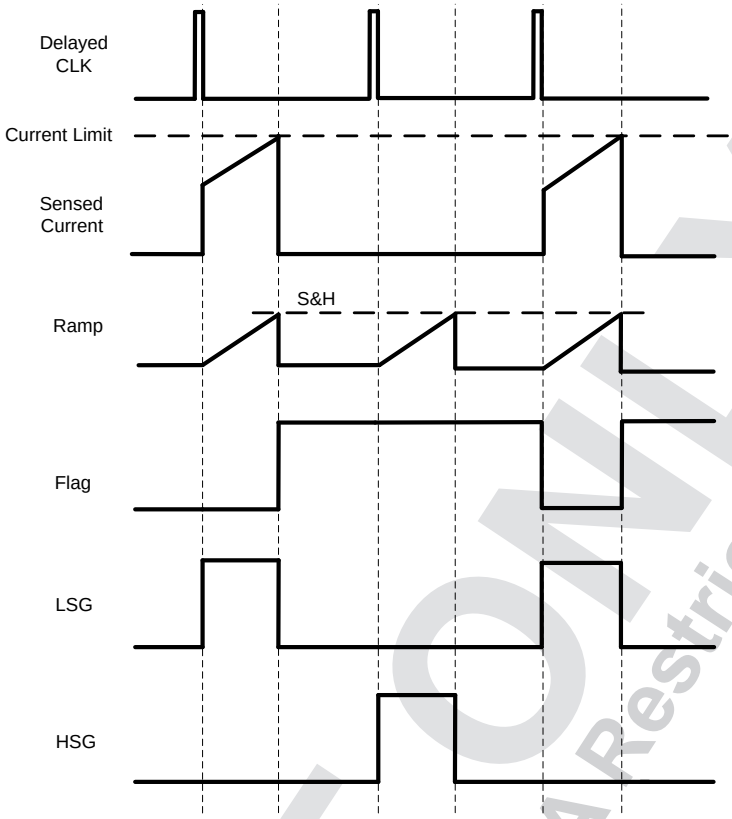


Figure 25. Pulse Matching Operation

7.3.12 Reverse Current Protection

In addition to the CBC current limit, a negative current limit, which is set to be half of the positive current limit as shown in Figure 26. This is used to prevent excessive reverse current which could cause significant output voltage dip and potentially damage the power converter. When the negative current limit is exceeded twice, the SSSR capacitor will be clamped to ground so the controller enters the SR SYNC mode where the SR pulses are synchronized to the respective primary FET pulses. Therefore, the SR freewheeling pulses are turned off. The negative current limit event counter will be reset if the number of negative current limit events detected within four switching periods is less than two.

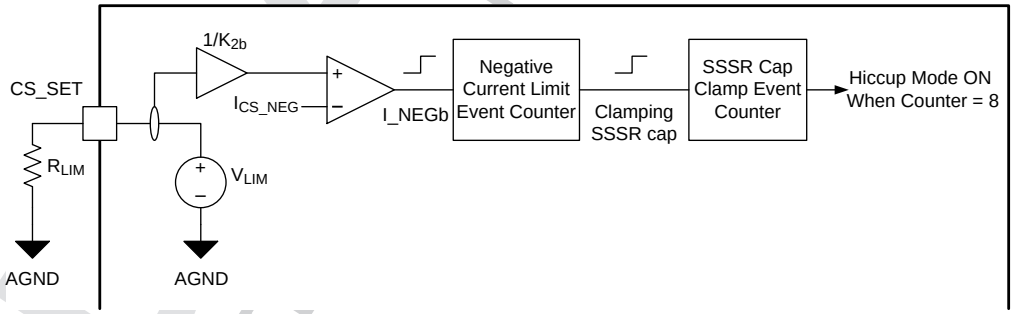


Figure 26. Reverse Current Protection Circuit

At the trip threshold of the NEG comparator both inputs are at the same potential. In this case the voltage on the CS_NEG pin is expressed by Equation 15.

$$V_{CS\_NEG} = I_{CS\_SET} \times \frac{1}{K_{2b}} \times K_{10b} \times R_3 \quad (15)$$

The voltage across the CS resistor at the trip threshold of the NEG comparator can therefore be determined by combining Equation 9, Equation 11 and Equation 15.

$$v_{CS\_NEGTh} = R_1 \times \left(\frac{K_{CBC2}}{R_{LIM}} - \frac{V_{IN}}{R_2} - I_{SLOPE} \times t_{CSBLK} \times f_{osc} \right)$$

Where :

$K_{2b} = 2$

$$K_{CBC2} = V_{LIM} \times \left(\frac{1}{K_{2b}} \times K_{10b} - K_{10a} \right) \quad (16)$$

Notice that the inductor current has its most negative value at the start of the LSG on period. The NEG comparator trip will occur immediately after the blanking period (t_{CSBLK}) has expired.

7.3.13 CBC Threshold Accuracy

The CBC current limit amplifier deployed within LM5036 is a precise component. In common with all such devices the input bias currents and input offset voltage will lead to small variations in the current trip threshold between parts and across temperature.

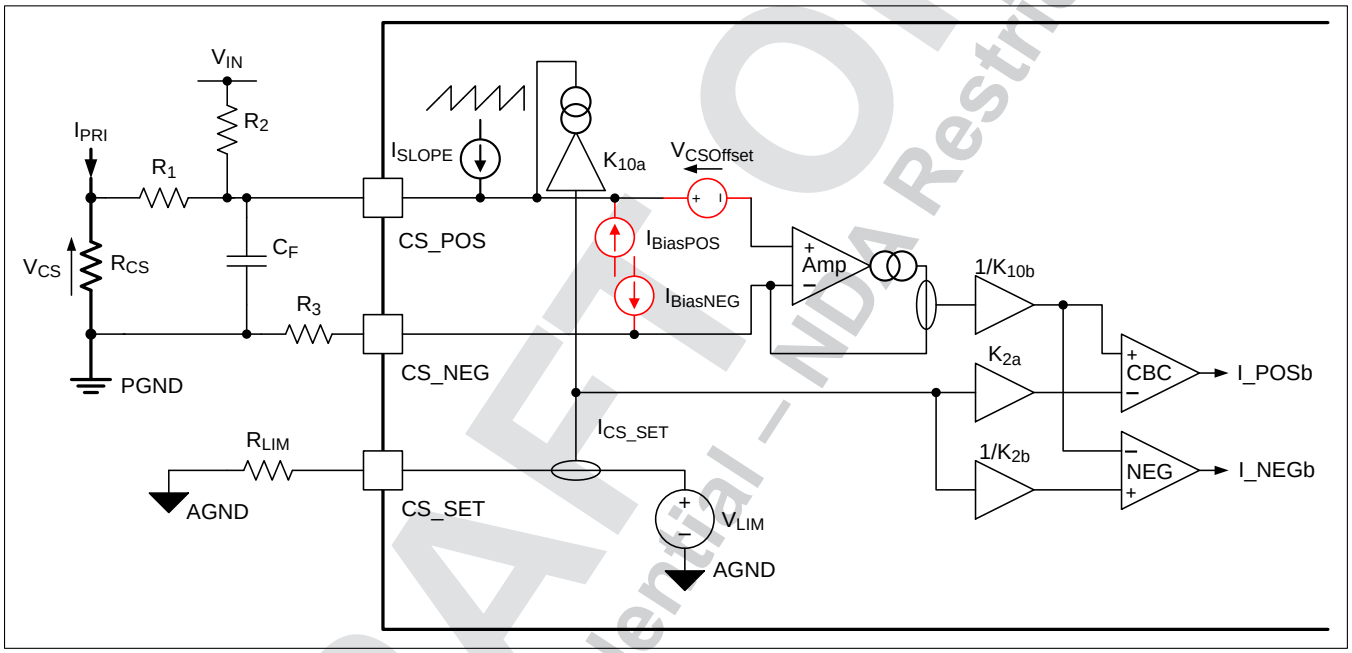


Figure 27. Diagram of Current Limiting Function with Error Terms Shown in Red

At its trip threshold the two inputs of the CBC comparator must be equal. At this condition the voltage on the CS_NEG pin is given by Equation 17.

$$v_{CS\_NEG} = \left(\frac{V_{LIM}}{R_{LIM}} \times K_{2a} \times K_{10b} + I_{BiasNEG} \right) \times R_3 \quad (17)$$

The voltage drop across the ideal amplifier input must be zero. The voltage of the CS_POS pin, at the trip threshold can be expressed as follows:

$$v_{CS\_POS} = v_{CS\_NEG} + v_{CSOffset} \quad (18)$$

$$v_{CS\_POS} = v_{CS\_CBCTh} + \left(\frac{V_{LIM}}{R_{LIM}} \times K_{10a} + I_{BiasPOS} + D \times I_{SLOPE} + \frac{V_{IN} - v_{CS\_POS}}{R_2} \right) \times R_1 \quad (19)$$

Combining Equation 17, Equation 18 and Equation 19 and re-arranging gives:

$$V_{CS\_CBCTh} = R_1 \times \left(\frac{K_{CBC1}}{R_{LIM}} - I_{BiasOffset} + \frac{V_{CSOffset}}{R_3} - D \times I_{SLOPE} - \frac{V_{IN}}{R_2} \right)$$

Where :

$$I_{BiasOffset} = I_{BiasPOS} - I_{BiasNEG}$$

(20)

Hence, for a given set of external component values, the variation in current trip threshold across parts and temperature can be found using data supplied in the Electrical Tables.

A short delay will exist (t_{CSLSG}), after the CBC comparator inputs reach their trip threshold, before the LSG falling edge. During this delay the primary current will continue to ramp, giving rise to a further error in the apparent trip threshold. The peak primary current flowing when the low side MOSFET switches OFF (I_{PriCBC}), is expressed by Equation 21.

$$I_{PriCBC} = \frac{V_{CS\_CBCTh}}{R_{CS}} + t_{CSLSG} \times \left(\frac{1}{2} \times \left(\frac{V_{IN}}{L_{Mag}} + \frac{V_{IN}}{L_O \times N_{PS}^2} \right) - \frac{V_O}{L_O \times N_{PS}} \right)$$

(21)

7.3.14 Impact of CBC Duty Cycle Mismatch on Output Current Limit

For a variety of reasons, including the difference in propagation delay of high and low side drivers, perfect matching of upper and lower duty cycle is not possible. Figure 28 illustrates the inductor current ripple waveform that exists when the t_{ON} time of the upper switch is slightly longer than the lower switch by a small amount 2 x Δt. This type of steady-state asymmetric ripple waveform impacts the relationship between output current limit and the CBC circuit components.

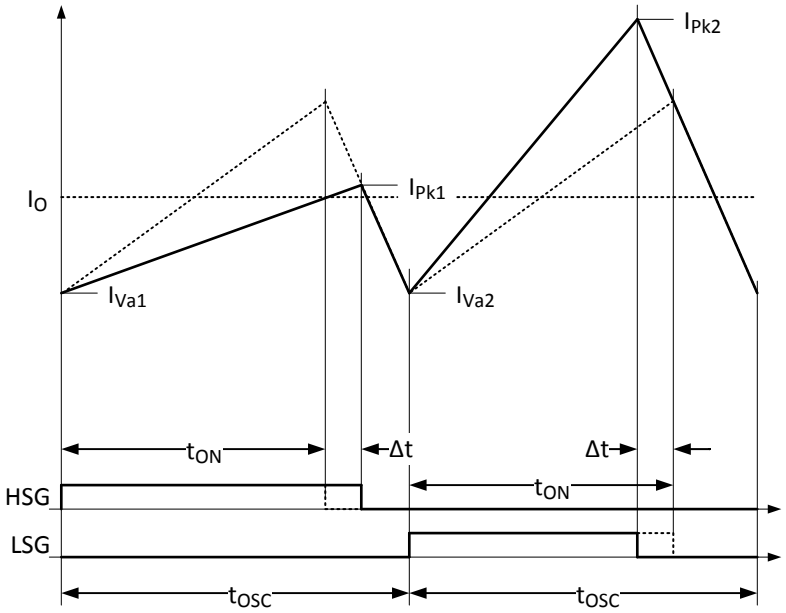


Figure 28. Output Inductor Current Waveform showing Impact of Duty Cycle Mismatch

For steady-state operation with mismatched duty cycle the output inductor current, splitter capacitor voltage and magnetising current must all return to their starting values at the end of a complete switching cycle. To ensure steady-state operation Equation 22, Equation 24 and Equation 29 must all be true.

$$\Delta I_{Mag} = \frac{(t_{ON} + \Delta t) \times V_{IN} \times (1 - x)}{2 \times L_{Mag}} = \frac{(t_{ON} - \Delta t) \times V_{IN} \times x}{2 \times L_{Mag}} \tag{22}$$

Where x is the fraction of V_{IN} that appears across the lower splitter capacitor. Based on Equation 22 an expression for x can be determined as a function of the duty cycle (D) and duty cycle mismatch (ΔD).

$$x = \frac{1}{2} \times \frac{D + \Delta D}{D}$$

Where

$$\Delta D = \Delta t \times f_{OSC} \tag{23}$$

Notice that for zero duty cycle mismatch (ΔD = 0) Equation 23 produces x = 1/2 as expected.

For the output inductor to be in steady-state the total volt-second product applied to the inductor over a complete switching cycle must equate to zero. This is expressed by Equation 24.

$$\left[\frac{V_{IN}\times(1-x)}{N_{PS}}-V_O\right]\times(t_{ON}+\Delta t)+\left[\frac{V_{IN}\times x}{N_{PS}}-V_O\right]\times(t_{ON}-\Delta t)=V_O\times\left[t_{OSC}-(t_{ON}+\Delta t)+t_{OSC}-(t_{ON}-\Delta t)\right] \quad (24)$$

Simplifying and substituting Equation 23 we arrive at a quadratic expression for the duty cycle required to achieve the required voltage gain Equation 25.

$$D-\frac{\Delta D^2}{D}=\frac{2\times V_O}{V_{IN}}\times N_{PS} \quad (25)$$

The quadratic Equation 25 can be solved to give Equation 26.

$$D=\frac{V_O}{V_{IN}}\times N_{PS}+\sqrt{\left(\frac{V_O}{V_{IN}}\times N_{PS}\right)^2+\Delta D^2} \quad (26)$$

Again for zero duty cycle mismatch (ΔD = 0) notice that Equation 26 becomes the same as the duty cycle expression given in Equation 13.

$$I_{Va2}=I_{Va1}+\frac{V_O\times\left[t_{OSC}-(t_{ON}-\Delta t)\right]}{L_O}-\frac{\left(\frac{V_{IN}\times x}{N_{PS}}-V_O\right)\times(t_{ON}-\Delta t)}{L_O} \quad (27)$$

Substituting Equation 23 and Equation 25 into Equation 27 gives the result Equation 28

$$I_{Va2}=I_{Va1} \quad (28)$$

Finally the current flowing into the splitter capacitors over a complete switching cycle must be zero. This is expressed by Equation 29.

$$\frac{I_{Va1}+I_{Pk1}}{4\times N_{PS}}\times(D+\Delta D)-\frac{I_{Va1}+I_{Pk2}}{4\times N_{PS}}\times(D-\Delta D)+I_{MagOffset}=0 \quad (29)$$

$$I_{Pk1}=I_{Va1}+\frac{V_O}{L_O\times f_{OSC}}\times\left[1-(D+\Delta D)\right] \quad (30)$$

$$I_{Pk2} = I_{Va1} + \frac{V_O}{L_O \times f_{OSC}} \times \left[1 - (D - \Delta D)\right] \quad (31)$$

Output current is equal to the inductor current averaged over a complete switching cycle.

$$I_O = \frac{I_{Va1}}{2} \times \frac{I_{Pk1} + I_{Pk2}}{4} \quad (32)$$

Hence we get Equation 33

$$I_{Va1} = I_O - \frac{V_O}{2 \times L_O \times f_{OSC}} \times (1 - D) \quad (33)$$

Substituting Equation 33 into Equation 29 gives Equation 34. $I_{MagOffset}$ is the DC component of magnetising current required to ensure that net current flowing into the splitter capacitors over a complete switching cycle is zero.

$$I_{MagOffset} = \frac{-I_{Va1}}{N_{PS}} \times \frac{\Delta D}{D} - \frac{V_O}{2 \times L_O \times f_{OSC} \times N_{PS}} \times \frac{\Delta D}{D} \times (1 - 2 \times D) \quad (34)$$

The peak primary current is given by Equation 35.

$$I_{PriPk} = \frac{I_{Pk2}}{N_{PS}} + \Delta I_{Mag} - I_{MagOffset} \quad (35)$$

Substituting Equation 31, Equation 33 and Equation 34 into Equation 35 gives an expression for the output current as a function of the peak primary current.

$$I_O = N_{PS} \times \frac{D}{D + \Delta D} \times \left[I_{PriPk} - \frac{V_O}{2 \times L_O \times f_{OSC} \times N_{PS}} \times (1 - D + \Delta D) - \frac{V_O \times N_{PS}}{2 \times L_{Mag} \times f_{OSC}} \right] \quad (36)$$

The output current limit level (I_{LIM}) can be found if the peak primary current flowing at the moment the low side MOSFET turns OFF (I_{PriCBC}) replaces the peak primary current in Equation 36.

$$I_{LIM} = N_{PS} \times \frac{D}{D + \Delta D} \times \left[I_{PriCBC} - \frac{V_O}{2 \times L_O \times f_{OSC} \times N_{PS}} \times (1 - D + \Delta D) - \frac{V_O \times N_{PS}}{2 \times L_{Mag} \times f_{OSC}} \right] \quad (37)$$

Equation 21 for the peak primary current, flowing as the lower MOSFET turns of, is adjusted to account for duty cycle mismatch to give Equation 38.

$$I_{PriCBC} = \frac{V_{CS\_CBCTh}}{R_{CS}} + t_{CSLSG} \times \left(\frac{1}{2} \times \frac{D + \Delta D}{D} \times \left(\frac{V_{IN}}{L_{Mag}} + \frac{V_{IN}}{L_O \times N_{PS}^2} \right) - \frac{V_O}{L_O \times N_{PS}} \right) \quad (38)$$

Equation 20 for CBC threshold voltage is adjusted to account for duty cycle mismatch to give Equation 39.

$$v_{CS\_CBCTh} = R_1 \times \left(\frac{K_{CBC1}}{R_{LIM}} - I_{BiasOffset} + \frac{v_{CSOffset}}{R_3} - I_{SLOPE} \times (D - \Delta D) - \frac{V_{IN}}{R_2} \right) \quad (39)$$

Substituting Equation 39 and Equation 38 into Equation 37 gives an expression for output current limit (I_{LIM}) in terms of circuit components and datasheet parameters.

Figure 29 illustrates the shift output current limit that occurs due to duty cycle mismatch during CBC operation. LM5036 and it integrated drivers offers excellent duty cycle matching so for most applications the impact on output current limit is small and may be neglected.

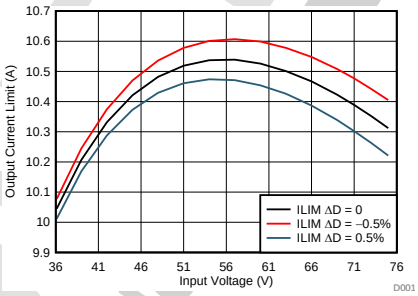


Figure 29. Output Current Limit vs Input Voltage Showing Effect of CBC Duty Cycle Mismatch

7.3.15 Hiccup Mode Protection

A block diagram of the hiccup mode function is shown in Figure 30. Both the repetitive CBC and negative current limit events will trigger hiccup mode operation in LM5036 device.

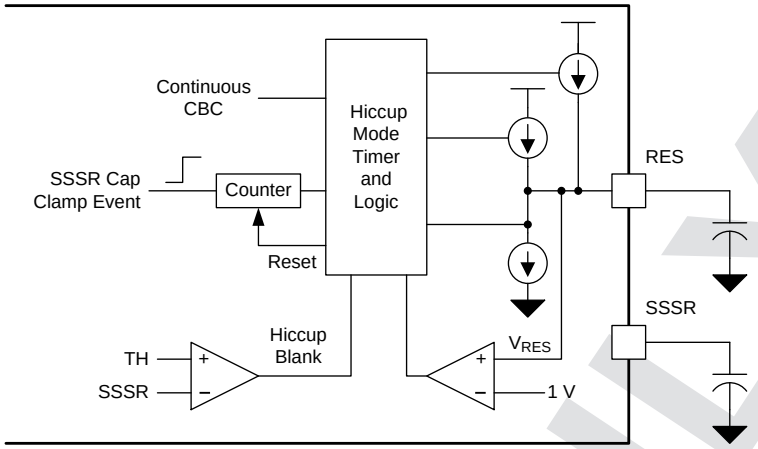


Figure 30. Hiccup Mode Circuitry

The device charges the hiccup restart capacitor with a 15-µA current source during CBC operation. The hiccup mode is activated when V_{RES} exceeds 1 V. During hiccup mode operation, the SS and SSSR capacitors are fully discharged and the half-bridge converter remains off for a period of time (t_{HIC}) before a new soft-start sequence is initiated.

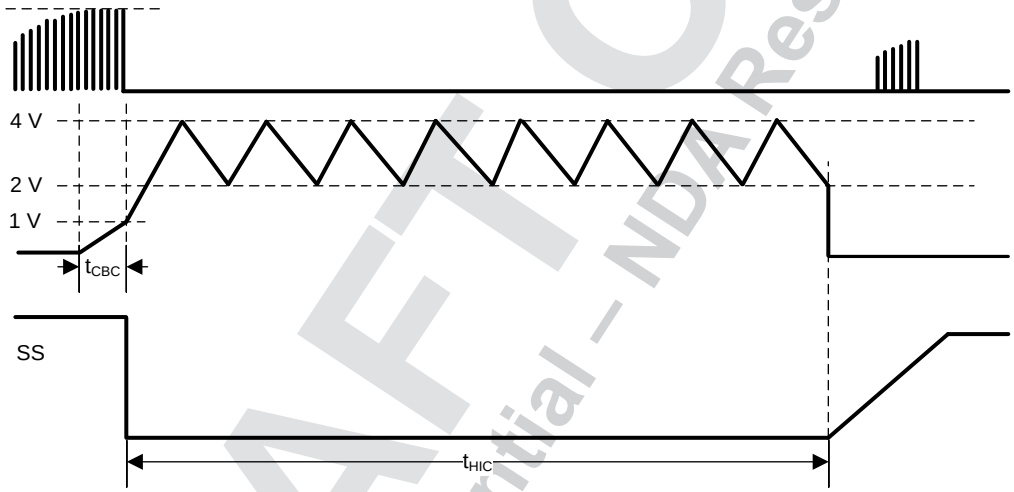


Figure 31. Hiccup Mode Activated By Continuous CBC Operation

Use Equation 40 to calculate the duration of CBC operation before entering the hiccup mode.

$$t_{CBC} = \frac{C_{RES} \times 1\ V}{15\ \mu A} \quad (40)$$

where

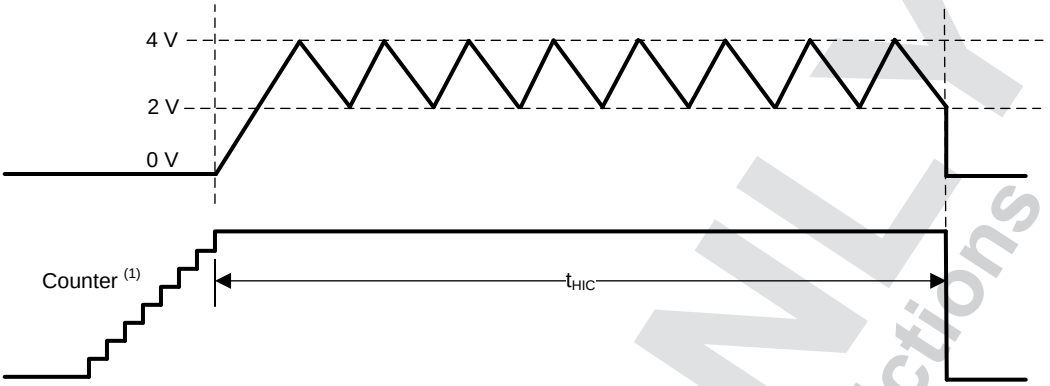
- C_{RES} is the value of the hiccup capacitor

After the RES pin reaches 1.0 V, the 15-µA current source is turned off and a 30-µA current source is turned on which charges the RES capacitor to 4 V. Then a current source of 5 µA is enabled which discharges the RES capacitor to 2 V.

Use Equation 41 to calculate the hiccup mode off-time.

$$t_{HIC} = \frac{C_{RES} \times 2\ V \times 8}{5\ \mu A} + \frac{C_{RES} \times (2\ V \times 8 + 1\ V)}{30\ \mu A} \quad (41)$$

In addition to the repetitive CBC current limit condition, the device also enters hiccup mode if the SSSR capacitor is clamped for eight times due to repetitive negative current limit condition. The operating pattern of the hiccup mode activated by the negative current limit is similar to that activated by CBC current limit. The only difference is that at the beginning of the hiccup mode operation the RES capacitor is charged with a 30-µA current source when activated by negative current limit as illustrated in Figure 32 whereas the RES capacitor is charged with a 15-µA current source when activated by CBC current limit condition.



(1) SSSR capacitor clamp event counter

Figure 32. Hiccup Mode Activated By Repetitive Negative OCP Condition

Once the hiccup off-timer expires, the SSSR capacitor clamp event counter will be reset. If SSSR capacitor gets clamped for less than eight times before the SSSR capacitor voltage is fully ramped up to its maximum value, the SSSR capacitor clamp event counter will also be reset. This is because the fact that SSSR capacitor voltage is able to fully ramp up to its maximum value indicates that repetitive negative current limit condition no longer exists.

7.3.16 Hiccup Mode Blanking

In some application scenarios such as high output capacitance and/or heavy load, there can be excessive inrush current during the start-up process. This would trigger CBC current limit which in turn activates the hiccup mode operation, thereby causing the converter to keep attempting to restart. In LM5036 device, a hiccup mode blanking circuitry is implemented to disable the hiccup mode operation during the start-up. The hiccup capacitor is clamped to ground until the SSSR capacitor voltage rises above the hiccup blank threshold.

7.3.17 Over-Temperature Protection (OTP)

Two-level internal thermal shutdown circuitry is implemented in LM5036 device to protect the integrated circuit in the event the maximum rated junction temperature is exceeded. When the internal temperature is above the lower-level threshold of 150°C, the half-bridge converter is turned off and thereby the SS and SSSR capacitors are fully discharged.

Typically, the internal temperature should drop after the main half-bridge converter is turned off. However, if the temperature continues to rise above the higher-level threshold of 160°C, the auxiliary supply will be disabled in order to prevent the device from catastrophic failures due to accidental device overheating . Note that the internal VCC and REF bias regulators still remain active during thermal shutdown to provide the bias power for the external house-keeping circuitry.

7.3.18 ON_OFF Pin

The ON_OFF pin can be configured as a latch pin or OVP pin. In the latch configuration, the half-bridge converter remains off even after the faults are cleared. A new soft-start sequence will not be initiated until the latch is reset. One latch configuration is illustrated in Figure 33 where a large latch resistor R_L (for example, 50 kΩ) and a diode are tied to the ON_OFF pin.

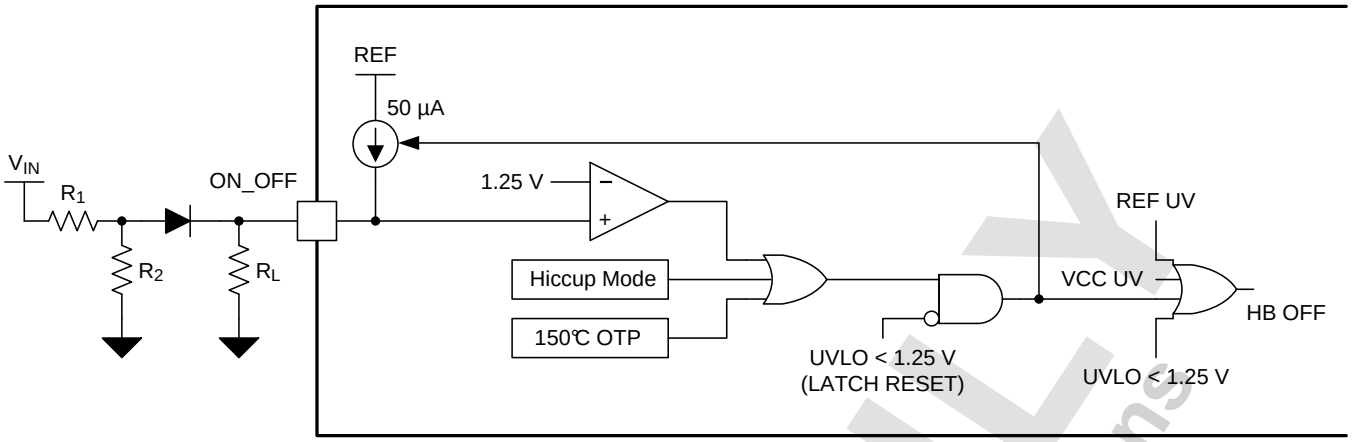


Figure 33. ON/OFF Pin Latch Function

When any of the faults is detected including OVP, hiccup mode OCP and 150 ºC OTP, the 50-µA ON_OFF pin current source is activated, which raise the ON_OFF pin voltage quickly. As a result, the latch diode is reverse biased. The current source remains active even if the fault is cleared because the ON_OFF pin voltage is latched above 1.25 V. To reset the latch operation, simply pulling down the UVLO pin voltage below 1.25 V which disables the current source and thus the ON_OFF pin voltage falls quickly. A new soft-start sequence will be initiated as soon as the latch is reset and the faults are cleared.

Use Equation 42 to design the external voltage divider in latch mode.

$$V_{IN\_L} = \left(\frac{1.25\ V + V_F}{R_2} + \frac{1.25\ V}{R_L}\right) \times R_1 + 1.25\ V + V_F \quad (42)$$

where

- where V_F is the forward voltage drop of the latch diode
- V_{IN_L} is the desired input voltage latch threshold, and R_L is the latch resistor.

Note that the current source does not provide any hysteresis when ON_OFF pin is configured in latch mode.

The ON_OFF pin can also be configured as an OVP pin as shown in Figure 34. In this configuration, the external voltage divider should be designed such that the ON_OFF pin voltage is greater than 1.25 V when over-voltage condition occurs.

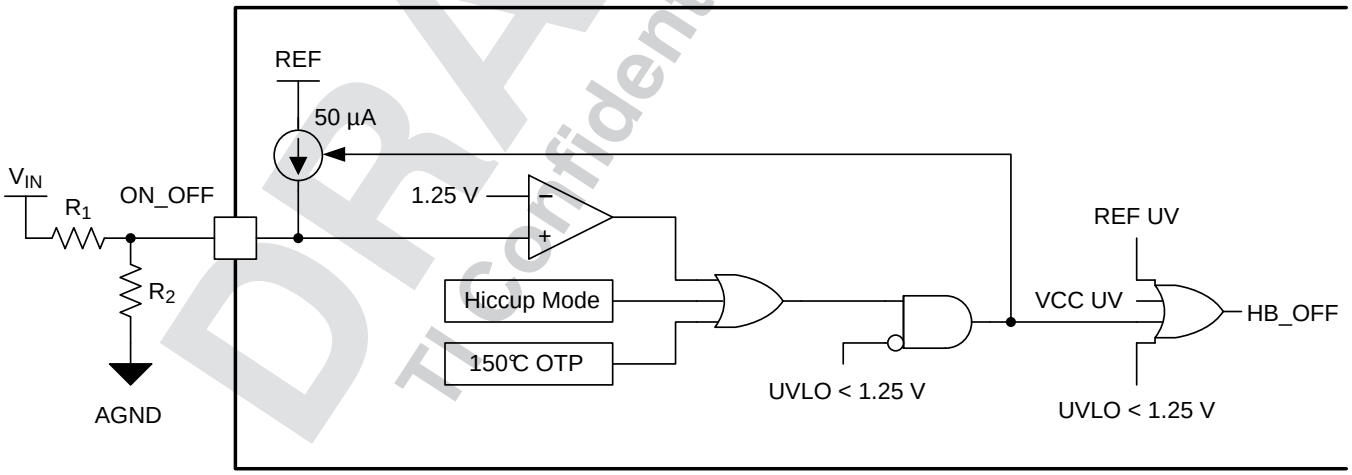


Figure 34. ON/OFF Pin Configured as OVP Pin

The OVP hysteresis is accomplished with the 50-µA current source. When the ON_OFF pin voltage exceeds 1.25 V, the 50-µA current source is activated which quickly raises the voltage at the pin. The half-bridge converter is turned off and the SS and SSSR capacitors are fully discharged. When the ON_OFF pin voltage falls below 1.25 V, the current source is deactivated causing the voltage at the pin to quickly fall followed by a new soft-start sequence. In addition to the OVP fault, hiccup mode and internal 150 ºC thermal shutdown faults will also cause the half-bridge converter to turn off. Once the faults are cleared, a new soft-start sequence automatically begins. Because the hiccup mode or 150 ºC thermal shutdown fault also activates the current source, it is important to make sure that the ON_OFF pin voltage doesn't rise above 1.25 V when the input voltage is high, which otherwise would lead to latch operation. Avoid this scenario by selecting a proper voltage divider.

Use Equation 43 and Equation 44 to select the voltage divider for the OVP configuration.

$$R_1 = \frac{V_{HYS\,(OVP)}}{50\ \mu A} \tag{43}$$

where

- $V_{HYS(OVP)}$ is the OVP hysteresis

$$R_2 = \frac{1.25\ V \times R_1}{V_{IN(OFF)} - 1.25\ V} \tag{44}$$

where

- $V_{IN(OFF)}$ is the OVP rising threshold

7.3.19 Auxiliary Constant On-Time Control

Figure 35 shows a block diagram of the constant on-time (COT) controlled fly-buck converter. The LM5036 device integrates an N-channel high-side MOSFET and associated high-voltage gate driver. The gate driver circuit works in conjunction with an external bootstrap capacitor and an internal high voltage diode. A 0.01-µF ceramic capacitor connected between the BST_AUX pin and SW_AUX pin provides the voltage to the driver during the on-time. During each off-time, the SW_AUX pin is at approximately 0 V, and the bootstrap capacitor charges from VCC through the internal diode. The minimum off-timer ensures a minimum time in each cycle to recharge the bootstrap capacitor. The LM5036 device also provides an internal N-channel SR MOSFET and associated driver. This MOSFET provides a path for the inductor current to flow when the high-side MOSFET is turned off.

The integrated auxiliary supply employs constant on-time (COT) hysteretic control which provides excellent transient response and ease of use. The control principle is based on a comparator and a one-shot on-timer, with the output voltage feedback (FB_AUX) compared to an internal reference. If the feedback voltage is below the reference the internal buck switch is switched on for the one-shot timer period, which is a function of the input voltage and the on-time resistor (R_{ON}). Following the on-time the switch remains off until the FB_AUX voltage falls below the reference, and the forced minimum off-time has expired. When the feedback voltage falls below the reference and the minimum off-time one-shot period expires, the high-side buck switch is then turned on for another on-time one-shot period. This will continue until regulation is achieved.

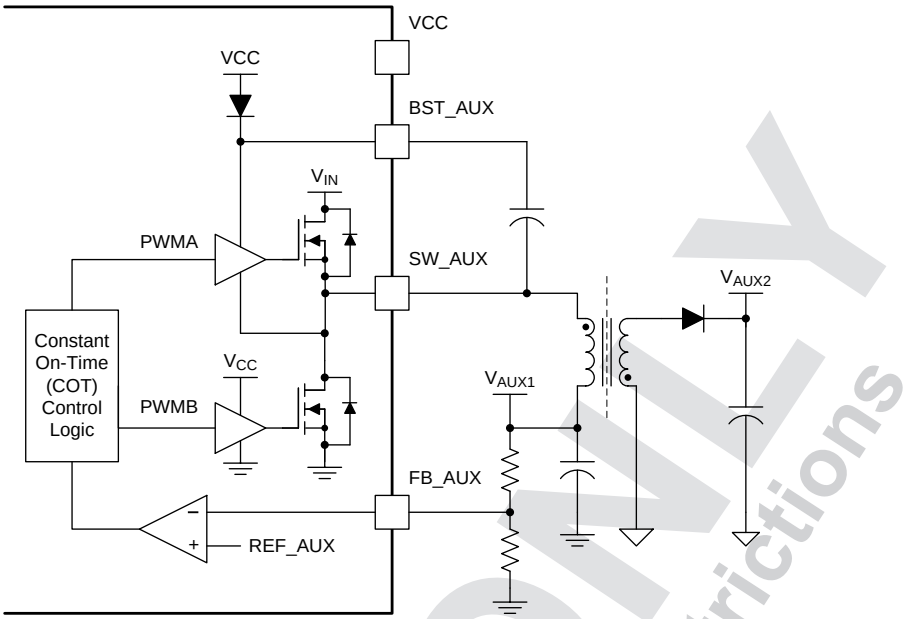


Figure 35. COT Controlled Fly-Buck Auxiliary Supply Circuitry

In a fly-buck converter, the low-side SR MOSFET is on when the high-side switch is off. The inductor current ramps up when the high-side switch is on and ramps down when the low-side switch is on.

The switching frequency remains relatively constant with load and line variations. Use Equation 45 to calculate the switching frequency of the auxiliary supply.

$$f_{SW\_AUX} = \frac{V_{AUX1}}{9 \times 10^{-11} \times R_{ON}} \quad (45)$$

where

- V_{AUX1} is the primary output voltage of the auxiliary supply.

Two external resistor values set the value of V_{AUX1}. This regulation of the output voltage depends on ripple voltage at the feedback input, requiring a minimum amount of ESR for the output capacitor (C_{AUX1}). A minimum of 25 mV of ripple voltage at the feedback pin is required for stable operation of the auxiliary supply. The *Auxiliary Ripple Configuration Types* section describes three types of auxiliary ripple circuit configurations.

7.3.20 Auxiliary On-Time Generator

The on-time for the auxiliary supply is determined by the resistor R_{ON}, and is inversely proportional to the input voltage, resulting in a nearly constant switching frequency as the input voltage is varied over its entire range. Figure 36 shows the block diagram for the on-time generator.

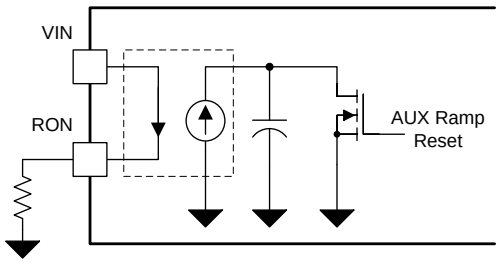


Figure 36. On-Time Generator

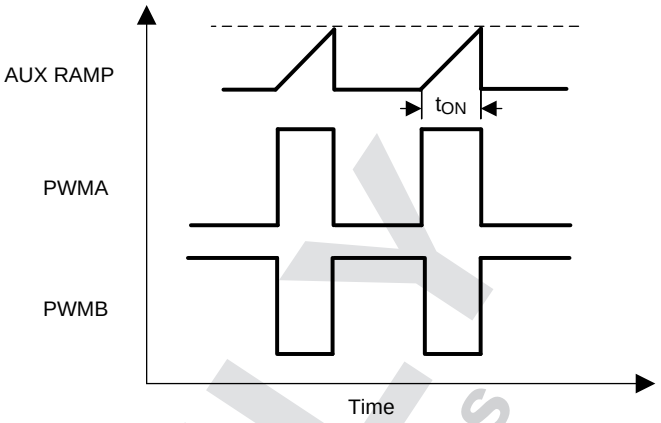


Figure 37. Constant On-Time Control Waveform

A current source, which is a function of the input voltage and the R_{ON} resistor value, charges a capacitor. The capacitor voltage ramps up linearly and gets reset when it reaches the threshold.

Use Equation 46 to calculate the on time t_{ON} of the high-side switch.

$$t_{ON} = \frac{9 \times 10^{-11} \times R_{ON}}{V_{IN}} \tag{46}$$

The R_{ON} should be selected for a minimum on-time (at maximum VIN) greater than 100 ns for proper operation. This requirement limits the maximum switching frequency according to Equation 45 and Equation 46.

7.3.21 Auxiliary Supply Current Limiting

The LM5036 device contains an intelligent current limit off-timer for the auxiliary supply. If the current in the high-side switch exceeds 200 mA typical, both the high-side MOSFET and the low-side SR are immediately turned off, and a non-resetable off-timer is initiated. The length of the off-time is a function of the FB_AUX voltage and the input voltage VIN. As an example, when V_{FB_AUX} = 0 V and V_{IN} = 48 V, a maximum off-time is set to 16 µs. This condition occurs when the output is shorted, and during the initial phase of start-up. This amount of time ensures safe short circuit operation up to the maximum input voltage of 100 V.

In cases of overload where the FB_AUX voltage is above zero volts (not a short circuit) the current limit off-time is reduced. Reducing the off-time during less severe overloads reduces the amount of foldback, recovery time, and start-up time. The current limit off-time is calculated from Equation 47.

$$t_{OFF\,(ILIM)} = \frac{(0.07 \times V_{IN})}{V_{FB\_AUX} + 0.2\,V}\ \mu s \tag{47}$$

Because the current limit protection feature of the auxiliary supply is peak limited, the maximum average output is less than the peak.

To prevent excessive reverse current during the off-time of the current limit, the auxiliary supply will operate at the asynchronous (ASYNC) mode where the low-side SR is turned off during the current limit operation.

Note that the minimum on-time of the high-side FET at the maximum VIN must be greater than the leading-edge blanking period for the current sense (95 ns typical). Otherwise, the current limit condition would not be detected. Due to the leading-edge blanking and propagation delay, the typical current limit response time for the auxiliary supply is 150 ns. Therefore, it is critical to ensure that the auxiliary transformer does not get saturated during this period, particularly under high-input voltage surge test where the rising slew-rate of the auxiliary transformer current is extremely fast. This can be accomplished by using an auxiliary transformer with adequate saturation current and inductance rating.

7.3.22 Auxiliary Ripple Configuration Types

With COT control, the on-time of the high-side FET is terminated by an on-timer, and the off-time is terminated when the feedback voltage (V_{FB_AUX}) falls below the reference voltage (V_{REF_AUX}). To maintain stable operation, the feedback voltage must decrease monotonically, in phase with the inductor current during the off-time. This change in feedback voltage during off-time must be large enough to suppress any noise component present at the feedback node.

The output voltage ripple has two components:

- ***Capacitive ripple*** caused by the inductor current ripple charging/discharging the output capacitor.
- ***Resistive ripple*** caused by the inductor current ripple flowing through the ESR of the output capacitor.

The capacitive ripple is not in phase with the inductor current. As a result, the capacitive ripple does not decrease monotonically during the off-time. The resistive ripple is in phase with the inductor current and decreases monotonically during the off-time. The resistive ripple must exceed the capacitive ripple at the output node for stable operation. If this condition is not satisfied unstable switching behavior is observed in COT converters, with multiple on-time bursts in close succession followed by a long off-time. Figure 38 through Figure 40 show three different methods for generating appropriate voltage ripple at the feedback node (SW_AUX).

7.3.22.1 Type 1

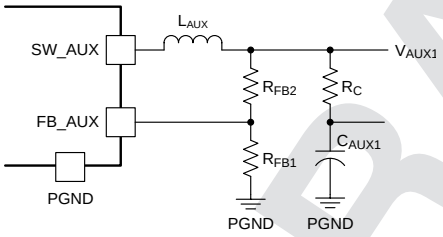
Figure 38 shows the lowest cost configuration. In cases where the capacitor ESR is too small, an additional series resistor R_C can be added to increase the ripple magnitude. For applications where lower output ripple voltage is required, the output can be taken directly from a low ESR output capacitor. However, R_C slightly degrades the load regulation.

7.3.22.2 Type 2

Figure 39 shows the reduced ripple configuration. The output voltage ripple is ac coupled to the feedback node through C_{ac}. Therefore, the value of R_C is reduced.

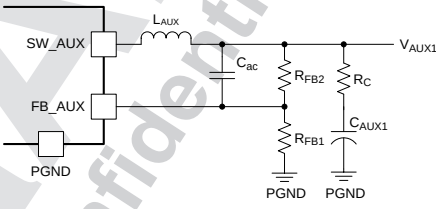
7.3.22.3 Type 3

Figure 40 shows the ripple method that uses R_r and C_r and the switch node voltage to generate a triangular ramp. This triangular ramp is ac coupled using C_{ac} to the feedback node. Because this circuit does not use the output voltage ripple, it is ideally suited for applications where low output voltage ripple is required. See AN-1481 Controlling Output Ripple and Achieving ESR Independence in Constant On-Time (COT) Regulator Designs for more details for each ripple generation method.



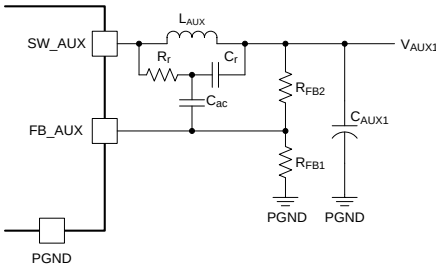
See Equation 48

Figure 38. Type 1: Lowest Cost Configuration



See Equation 49 and Equation 50

Figure 39. Type 2: Reduced Ripple Configuration



See Equation 53, Cr = 1000 pF, Cac = 100 nF

Figure 40. Type 3: Minimum Ripple Configuration

$$R_C \geq \frac{25\ mV}{\Delta I_{L(AUX)\_min}} \times \frac{V_{AUX1}}{V_{REF\_AUX}} \quad (48)$$

$$C_{ac} \geq \frac{5}{f_{SW\_AUX} \times (R_{FB2} \,||\, R_{FB1})} \quad (49)$$

$$R_C \geq \frac{25\ mV}{\Delta I_{L(AUX)\_min}} \quad (50)$$

C_r = 1000 pF (51)

C_{ac} = 100 nF (52)

$$R_r \times C_r \leq \frac{(V_{IN(min)} - V_{AUX1}) \times t_{ON(min)}}{25\ mV} \quad (53)$$

7.3.23 Asynchronous Mode Operation of Auxiliary Supply

In LM5036 device, there are two conditions where the auxiliary supply will enter asynchronous (ASYNC) mode operation where the low-side SR is turned off and only its body diode is allowed to conduct. The first condition is when the half-bridge converter is turned off (Refer to the *Device Functional Modes* section). This helps to reduce the power consumption of the auxiliary supply at light loads. As described in the *Auxiliary Supply Current Limiting* section, the auxiliary supply will also be forced to operate at ASYNC mode during current limit operation to prevent excessive reverse current.

7.4 Device Functional Modes

The functional modes of the device are summarized in the following table. Faults include hiccup mode OCP, OVP, and 150°C OTP.

Table 1. Device Functional Modes

CRITERIA	VCC AND REF REGULATORS	AUXILIARY SUPPLY	HALF-BRIDGE CONVERTER
UVLO < 0.35 V	OFF	OFF	OFF
(0.35 V < UVLO < 1.25 V) & (VIN < 15 V)	ON	OFF	OFF
(0.35 V < UVLO < 1.25 V) & (VCC & REF > UV) & (VIN > 15 V)	ON	ON at ASYNC Mode	OFF
(UVLO > 1.25 V) & (VIN > 15 V) & (VCC & REF > UV) & No Faults	ON	ON at SYNC Mode	ON
(UVLO > 1.25 V) & (VIN > 15 V) & (VCC & REF > UV) & Any Faults	ON	ON at ASYNC Mode	OFF
(VCC & REF > UV) & (VIN > 15 V) & AUX Current Limit	ON	ON at ASYNC Mode	NA

8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The LM5036 device is a highly integrated half-bridge PWM controller that contains all the features necessary for implementing the half-bridge topology power converters using voltage-mode control with input voltage feed-forward. The device targets isolated DC-DC converter applications with input voltage of up to 100 V_{DC}.

8.2 Typical Application

The following schematic shows an example of an isolated half-bridge DC-DC converter controlled by LM5036 device. The operating input voltage range is 36 V to 75 V, and the output voltage is 12 V. The maximum load current is 8 A and the output current limit is configured to be 10 A.

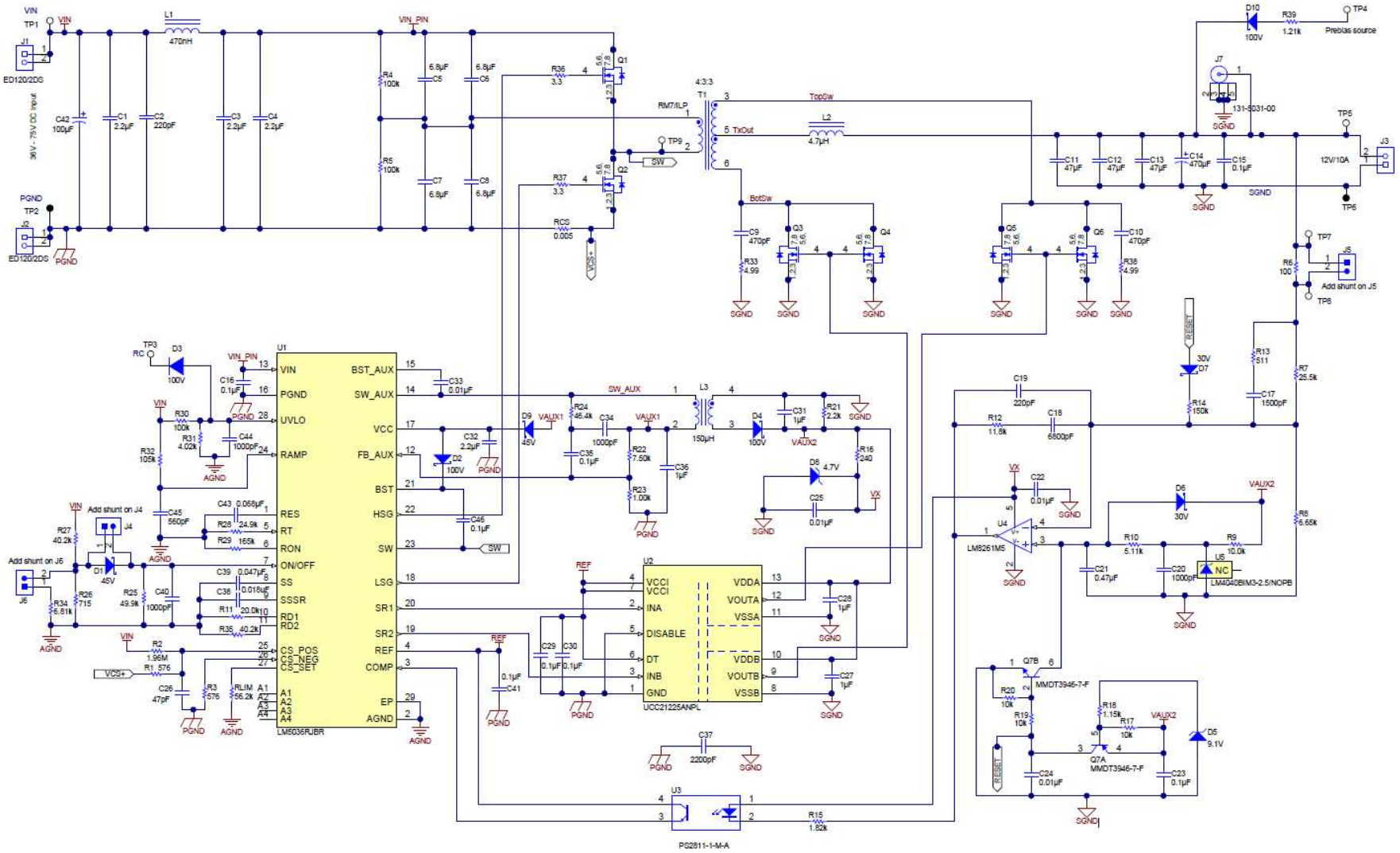


Figure 41. Evaluation Board Schematic

8.2.1 Design Requirements

PARAMETER		VALUE
V_{IN}	Input voltage	36 V to 75 V
V_O	Output voltage	12 V
$I_{O(max)}$	Maximum load current	8 A
I_{LIM}	Output current limit	10 A
η	Peak efficiency	94.41%
	Efficiency at V_{IN} = 48 V and I_O = 8 A	93.46%
V_{AUX1_OFF}	Off-state auxiliary output voltage	12.6 V
V_{AUX1_ON}	On-state auxiliary output voltage	9 V
	Load regulation	0.2%
	Line regulation	0.1%
	Line UVLO rising/falling threshold	34 V/32 V
	Line OVP rising/falling threshold	80 V/78 V
	Latch threshold	80 V
	Maximum load current for auxiliary supply	100 mA

8.2.2 Detailed Design Procedure

8.2.2.1 Custom Design With WEBENCH® Tools

Click here to create a custom design using the LM5036 device with the WEBENCH® Power Designer.

1. Start by entering the input voltage (V_{IN}), output voltage (V_{OUT}), and output current (I_{OUT}) requirements.
2. Optimize the design for key parameters such as efficiency, footprint, and cost using the optimizer dial.
3. Compare the generated design with other possible solutions from Texas Instruments.

The WEBENCH Power Designer provides a customized schematic along with a list of materials with real-time pricing and component availability.

In most cases, these actions are available:

- Run electrical simulations to see important waveforms and circuit performance
- Run thermal simulations to understand board thermal performance
- Export customized schematic and layout into popular CAD formats
- Print PDF reports for the design, and share the design with colleagues

Get more information about WEBENCH tools at www.ti.com/WEBENCH.

8.2.2.2 Input Transient Protection

The voltage applied to the VIN pin of LM5036 device serves as the input voltage for the internal VCC startup regulator and auxiliary supply. In typical applications, the VIN pin voltage is the same as the input voltage for the main half-bridge converter. The recommended range of the VIN pin voltage is 18 V to 100 V. Figure 42 shows the recommended filter that suppresses the transients that may occur at the input supply. This suppression is particularly important when the input voltage rises to a level near the maximum recommended operating rating (100 V) of the LM5036 device.

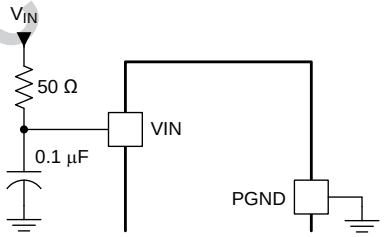


Figure 42. Input Transient Protection

8.2.2.3 Level-Shift Detection Circuit

An example implementation of the V_{AUX2} level-shift detection circuit is shown in Figure 43. The zener voltage must be between the off-state and on-state level of V_{AUX2}. When V_{AUX2} is above the zener voltage, both Q1A and Q1B are turned on and therefore the reference output voltage V_{REF} is clamped to ground. Once V_{AUX2} falls below the zener voltage, both Q1A and Q1B are turned off, and the reference is released.

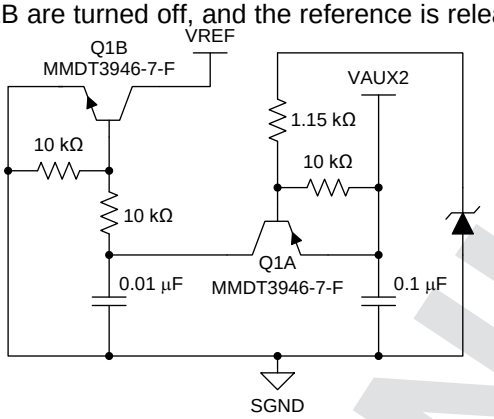


Figure 43. Secondary Auxiliary Voltage Level-Shift Detection Circuit

8.2.2.4 Applications with V_{IN} > 100 V

For applications where the input voltage exceeds 100 V, all of the 100V-rated internal circuit blocks, including VCC start-up regulator, auxiliary supply and half-bridge gate drivers, need to be bypassed. In this case, VIN pin can be powered from an external start-up regulator, as shown in Figure 44. The VIN and VCC pins should be tied together in this configuration. The voltage at the VCC and VIN pins must be greater than the maximum internal VCC voltage yet not exceed the maximum recommended rating. The external bias supply V_{AUX1}, can be derived from an external auxiliary supply. An external gate driver with higher voltage rating should be used to drive the half bridge.

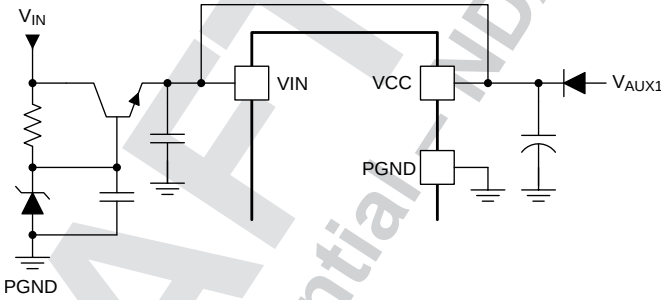


Figure 44. External Start-Up Regulator

8.2.2.5 Applications without Pre-Biased Start-Up Requirement

For applications where the pre-biased startup is not required, the level-shift detection circuit described in the *Pre-Biased Start-Up Process* section is not necessary. Without the level-shift detection circuit, the reference voltage on the secondary side would be released as soon as the secondary bias is established. The external VCC bias supply can be derived from the integrated auxiliary supply or an auxiliary winding of the main transformer.

8.2.2.6 UVLO Voltage Divider Selection

As described in the *Undervoltage Lockout (UVLO)* section, two external resistors can be used to program the minimum operating voltage for the power converter, as shown in Figure 45. When the UVLO pin voltage falls below 1.25-V threshold, an internal 20-µA current sink is enabled to lower the voltage at the UVLO pin, thus providing the threshold hysteresis. Resistance values for R_1 and R_2 can be determined from Equation 54 and Equation 55.

$$R_1 = \frac{V_{HYS\ (UVLO\ )}}{20\ \mu A}$$

where

- $V_{HYS(UVLO)}$ is the UVLO hysteresis (54)

$$R_2 = \frac{1.25\ V \times R_1}{V_{IN(on)} - 1.25\ V - 20\ \mu A \times R_1}$$

where

- $V_{IN(on)}$ is the input voltage UVLO rising threshold. (55)

Figure 46 illustrates one way to configure a latch reset operation by pulling the UVLO pin voltage below 1.25 V. The diode voltage drop must be between 0.35 V and 1.25 V. The controller can be forced to enter shutdown mode by pulling UVLO pin to GND.

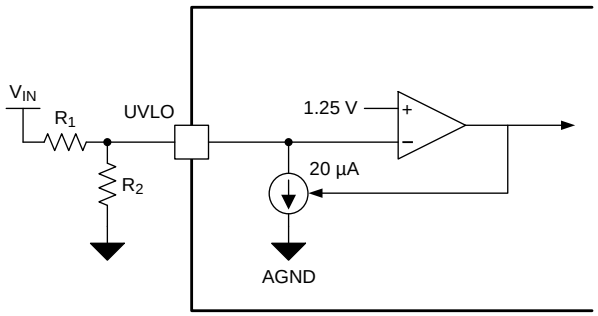


Figure 45. UVLO Configuration

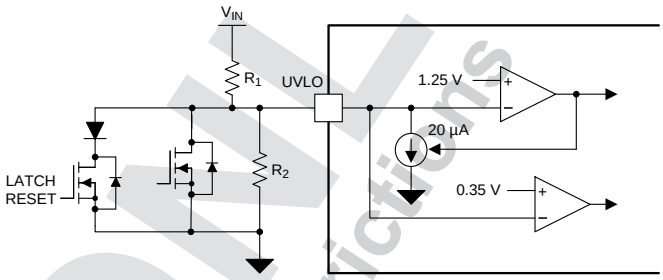


Figure 46. Latch Reset

8.2.2.7 ON_OFF Pin Voltage Divider Selection

As described in the *ON_OFF Pin* section, the ON_OFF pin can be configured as a latch pin or an OVP pin. Figure 33 shows the latch configuration. The ON_OFF pin is latched when the pin voltage reaches 50 µA × R_L when any of the internal faults is detected. The latch diode is reverse-biased during latch operation. The latch resistor R_L should be selected such that 50 µA × R_L > 1.25 V. In this design example, R_L is selected to be 49.9 kΩ. If the latch threshold is 80 V, R_1 should be 40 kΩ, and R_2 should be 710 Ω.

If the ON_OFF pin is configured as an OVP pin, two resistors can be used to program the maximum operating input voltage for the half-bridge converter, as illustrated in Figure 34. When the ON_OFF pin voltage rises above the 1.25-V threshold, an internal 50-µA current source is enabled to raise the ON_OFF pin voltage, thus providing the threshold hysteresis. Use Equation 43 and Equation 44 to determine resistance values for R_1 and R_2. If the LM5036 device is to be disabled when $V_{IN(OFF)}$ reaches 80 V and enabled when it is decreased to 78 V. R_1 should be 40 kΩ, and R_2 should be 635 Ω. In addition, the ON_OFF pin can also be used for external thermal protection with a thermistor.

8.2.2.8 SS Capacitor

The soft-start delay $t_{D(SS)}$, which is the time it takes for the soft-start capacitor to rise from 0 V to 2 V, can be programmed with the SS capacitor value according to Equation 56

$$C_{SS} = \frac{I_{SS} \times t_{D(SS)}}{2\ V}$$

where

- I_{SS} = 20 µA (typical) is the current source of the soft-start pin (56)

8.2.2.9 SSSR Capacitor

The SSSR capacitor value determines the rate at which the pulse width of the SR's of the half-bridge converter increases. To achieve a monotonic start-up for the output voltage, the SSSR capacitor value should satisfy the following two conditions:

- SR soft-start sequence should be completed before regulation set-point of the output voltage is reached.
- With a lower control loop bandwidth, the primary-side duty cycle tends to increase at a slower rate. Therefore the ramp-up speed of the SSSR capacitor voltage should be reduced accordingly in order to prevent excessive reverse current.

A general rule of thumb is to maintain the control loop bandwidth of the half-bridge converter above 1 kHz. With a slow control loop bandwidth, the output voltage needs to drop at least 25% from the regulation set-point during the restart time period where the SS pin voltage rises from 0 V to 2 V and then the secondary-side reference V_{REF} rises to 75% of regulation set-point. To satisfy the first condition above, the rise time of the SSSR capacitor voltage should be less than 25% of the rise time of the output voltage, as described in Equation 57.

$$C_{SSSR} < \frac{I_{SSSR} \times 25\% \times t_{RAMP}}{5\ V} \quad (57)$$

where

- I_{SSSR} = 20 µA (typical) is the current source of the SSSR pin. t_{RAMP} is the ramp-up time of the output voltage.

Use the SSSR capacitor value calculated from Equation 57 as a starting point. Fine-tuning may be needed based on the actual control loop design and other specific design requirements such as pre-bias conditions and loading profile.

8.2.2.10 Current Limit

The *Enhanced Cycle-by-Cycle Current Limiting with Pulse Matching* section describes the CBC current limiting functionality in detail. Figure 47 illustrates the current limiting block diagram of the LM5036 device. There are five resistors associated with the current limiting function of the half-bridge converter, as listed below:

- R_{CS}
- R_3
- R_2
- R_{LIM}
- R_1

Because R_3 is equal to the equivalent resistance of R_1 and R_2 as given by Equation 13, there are four unknown resistor values to be determined.

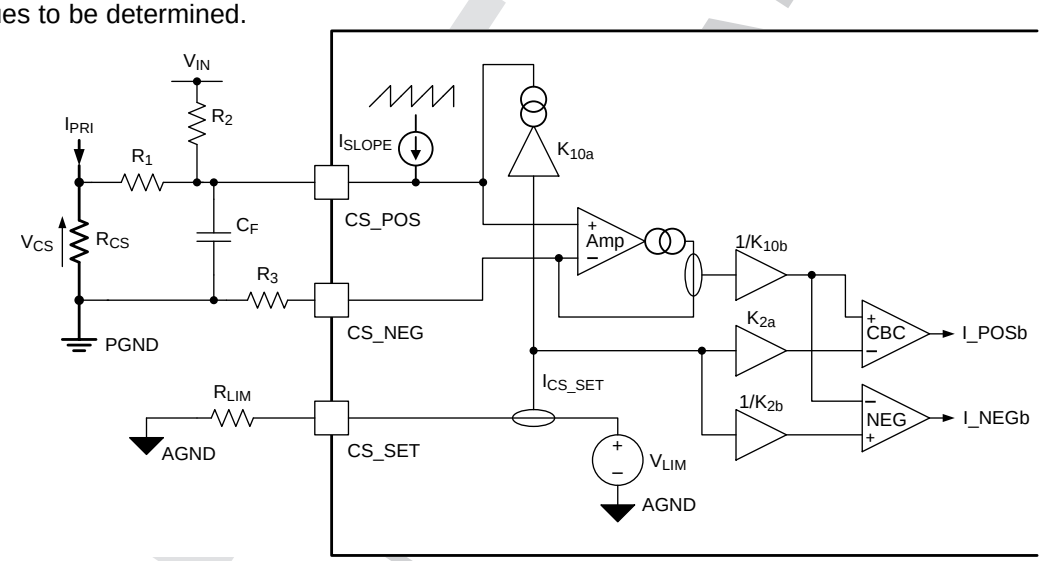


Figure 47. Current Limiting Block

The value of current sense resistor R_{CS} is determined based on the maximum power consumption requirement. Typically, the current sense resistor should consume less than 0.5% of the input power of the converter at the worst case scenario. The sense resistor conducts every alternate current pulse flowing in the primary winding. The power dissipated in the sense resistor is determined by Equation 58.

$$P_{CS} = \frac{I_{Pri\_RMS}^2}{2} \times R_{CS} \quad (58)$$

The RMS current flowing in the primary winding may be calculated using Equation 59.

$$I_{Pri\_RMS} = \frac{I_O}{N_{PS}} \times \sqrt{D \times \left(1 + \frac{1}{3} \times \left(\frac{\Delta I_{Pri}}{I_O}\right)^2\right)}$$

Where :

$$\Delta I_{Pri} = \frac{\Delta I_{LO}}{N_{PS}} + \Delta I_{LMag} = \frac{V_O}{2 \times L_O \times N_{PS}} \times \left(\frac{1-D}{f_{OSC}}\right) + \frac{V_{IN}}{4 \times L_{Mag}} \times \frac{D}{f_{OSC}} \quad (59)$$

Maximum loss in the current sense resistor will occur while maximum output current (I_{LIM}) is delivered from minimum input voltage ($V_{IN(min)}$). Evaluating Equation 59 gives Equation 60.

$$I_{Pri\_RMS} = 7.07A \quad (60)$$

To achieve our target of dissipating less than 0.5% of maximum output power the current sense resistor must satisfy Equation 61.

$$R_{CS} < 0.5\% \times V_O \times I_{LIM} \times \frac{2}{I_{Pri\_RMS}^2} = 0.024\ \Omega \quad (61)$$

In our example design the current sense resistor value selected is given in Equation 62.

$$R_{CS} = 5\ m\Omega \quad (62)$$

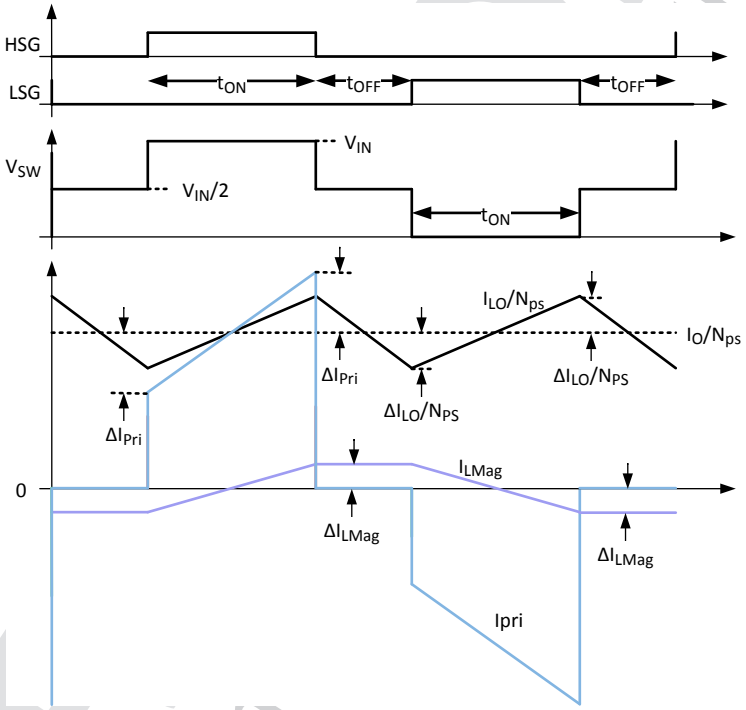


Figure 48. Main Converter Operating Waveforms

The resistor R_1 is used to set the slope compensation magnitude. In LM5036 device, the slope of the compensation ramp is given by Equation 63. To eliminate sub-harmonic oscillation, m_C should be set to at least one-half the down-slope of output inductor current transformed to the primary side across the current sense resistor, as given by Equation 64 and Equation 65. To damp the sub-harmonic oscillation after one cycle, m_C must be set equal to one times the down-slope of the output inductor current. This configuration is known as deadbeat control. In LM5036 device, the slope compensation signal is a saw-tooth current waveform of magnitude I_{SLOPE} at the oscillator frequency (twice the switching frequency).

$$m_C = I_{SLOPE} \times f_{OSC} \times R_1$$

where

- Where m_C is the slope of the compensation ramp

- I_{SLOPE} is the amplitude of the saw-tooth current signal used for slope compensation

(63)

$$m_L = \frac{V_O}{L_O} \times \frac{1}{N_{PS}} \times R_{CS} = 9.57 \frac{mV}{\mu s}$$

where

- m_L is the down-slope of the output inductor current transformed to the primary side
- N_P is the number of turns for the primary winding of the main transformer
- N_S is the number of turns for the secondary winding of the main transformer
- V_O is the output voltage of the half-bridge converter
- L_O is the output inductor value of the half-bridge converter
- R_{CS} is the current sense resistor

(64)

$$m_C > \frac{1}{2} \times m_L \tag{65}$$

Substituting Equation 63 and Equation 64 into Equation 65 gives us an expression for the minimum value for resistor R_1 to avoid sub-harmonic oscillation.

$$R_1 > \frac{1}{2} \times \frac{V_O}{L_O} \times \frac{1}{N_{PS}} \times R_{CS} \times \frac{1}{I_{SLOPE} \times f_{OSC}} = 239\ \Omega \tag{66}$$

Deadbeat control is ensured by doubling this value. For our example design the value given in Equation 67 has been selected

$$R_1 = 576\ \Omega \tag{67}$$

Values have now been selected for both R_{CS} and R_1. Values for R_{LIM} and R_2 are yet to be determined. These values define the peak current limit threshold and how this level will vary with input voltage. The relationship between peak primary current limit and maximum output current is defined by Equation 36, Equation 38 and Equation 39. For this design example we will neglect $I_{BiasOffset}$, $V_{CSOffset}$ and duty cycle mismatch ΔD. Since these parameters have only a small effect on output current limit. Setting all these parameters to zero we arrive at Equation 68, Equation 69 and Equation 70.

$$I_O(V_{IN}, R_{LIM}, R_2) = N_{PS} \times \left[I_{PriCBC}(V_{IN}, R_{LIM}, R_2) - \frac{V_O}{2 \times L_O \times f_{OSC} \times N_{PS}} \times (1 - D) - \frac{V_O \times N_{PS}}{2 \times L_{Mag} \times f_{OSC}} \right] \tag{68}$$

$$I_{PriCBC}(V_{IN}, R_{LIM}, R_2) = \frac{V_{CS\_CBCTh}(V_{IN}, R_{LIM}, R_2)}{R_{CS}} + t_{CSLSG} \times \left(\frac{1}{2} \times \left(\frac{V_{IN}}{L_{Mag}} + \frac{V_{IN}}{L_O \times {N_{PS}}^2} \right) - \frac{V_O}{L_O \times N_{PS}} \right) \tag{69}$$

$$V_{CS\_CBCTh}(V_{IN}, R_{LIM}, R_2) = R_1 \times \left(\frac{K_{CBC1}}{R_{LIM}} - I_{SLOPE} \times D - \frac{V_{IN}}{R_2} \right) \tag{70}$$

The output current limit will vary with input voltage. For this design example the output current limit is set to I_{LIM} at the extremes of input voltage giving Equation 71 and Equation 72. This is done to limit the spread of output current limit across the range of input voltage.

$$I_O(V_{IN(min)}, R_{LIM}, R_2) = I_{LIM} \tag{71}$$

$$I_O(V_{IN(max)}, R_{LIM}, R_2) = I_{LIM} \tag{72}$$

Solving Equation 71 and Equation 72 simultaneously yields values for resistors R_{LIM} and R_2.

$$R_2 = \frac{1}{\frac{t_{CSLSG}}{2} \times \frac{R_{CS}}{R_1 \times N_{PS}} \times \left(\frac{1}{L_{Mag}} + \frac{1}{L_O \times {N_{PS}}^2} \right) - \frac{1}{V_{IN(min)} \times V_{IN(max)}} \left(\frac{{V_O}^2}{L_O \times f_{OSC}} \times \frac{R_{CS}}{R_1} - I_{SLOPE} \times 2 \times V_O \times N_{PS} \right)} = 2.33\ M\Omega \tag{73}$$

$$R_{LIM} = \frac{K_{CBC1}}{\frac{R_{CS}}{R_1} \times \left[\frac{I_{LIM}}{N_{PS}} + \frac{V_O}{2 \times L_O \times N_{PS} \times f_{OSC}} \times \left(1 - \frac{2 \times V_O \times N_{PS}}{V_{IN(min)}} \right) + \frac{V_O \times N_{PS}}{2 \times L_{Mag} \times f_{OSC}} - \frac{t_{CSLSG}}{N_{PS}} \times \left[\frac{V_{IN(min)}}{2 \times L_{Mag}} + \frac{V_{IN(min)}}{2 \times L_O \times N_{PS}^2} - \frac{V_O}{L_O \times N_{PS}} \right] \right] + I_{SLOPE} \times \frac{2 \times V_O \times N_{PS}}{V_{IN(min)}} + \frac{V_{IN(min)}}{R_2}} = 56.9\ k\Omega$$

(74)

Having determined values for R_1 and R_2, the value of resistor R_3 is fixed by Equation 13.

The selected values for R_2 and R_{LIM} are given in Equation 75. Figure 49 presents the measured output current limit vs input voltage for the circuit presented in Figure 41. Figure 49 also presents the output current limit vs line for the same circuit predicted by Equation 68, Equation 69 and Equation 70. There is good agreement between measured and predicted results.

$$R_2 = 1.96\ M\Omega$$
$$R_{LIM} = 56.2\ k\Omega \quad (75)$$

If the magnitude of the leading-edge spike is excessive, an additional filter capacitor C_F should be added to form and RC filter with R_1 to reduce the high-frequency noise spike. The time constant of this RC filter must be short compared with the shortest t_{ON} period to avoid affecting the current limit set point. Both the leading-edge blanking and the RC filter help to prevent false triggering of the CBC current limiting operation.

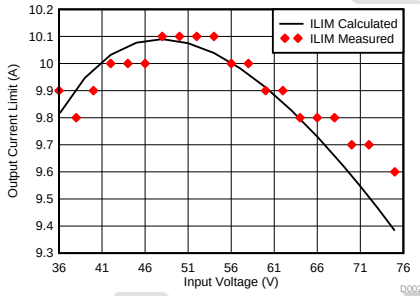


Figure 49. Main Converter Measured vs Predicted Output Current Limit

8.2.2.11 Auxiliary Transformer

A coupled inductor or a flyback-type transformer is required for this fly-buck topology auxiliary supply. Energy is transferred from primary to secondary when the low-side SR MOSFET is conducting.

The transformer turns ratio is selected based on the ratio of the primary output voltage to the secondary output voltage. In this design example, the two outputs are set to be equal and a 1:1 turns ratio transformer is selected, i.e., $N_2/N_1 = 1$. If the secondary output voltage is significantly higher or lower than the primary output voltage, a turns ratio less than or greater than 1 is recommended. The primary output voltage is normally selected based on the input voltage range such that the duty cycle of the converter does not exceed 50% at the minimum input voltage. This condition is satisfied if $V_{AUX1} < V_{IN(min)} / 2$.

Use Equation 76 to calculate the maximum peak-to-peak inductor current ripple $\Delta I_{L(AUX)}$ that can be tolerated without exceeding the peak current limit threshold (150 mA minimum) of the high-side switch,

$$\Delta I_{L(AUX)} = \left(0.15 - I_{AUX1} - I_{AUX2} \times \frac{N_2}{N_1} \right) \times 2$$

where

- I_{AUX1} is the primary output current, and I_{AUX2} is the secondary output current of the auxiliary supply, respectively.

(76)

In this design example, the maximum total output current $I_{AUX(max)}$ of the auxiliary supply referred to the primary side is 100 mA, as given by Equation 77.

$$I_{AUX(max)} = I_{AUX1} + I_{AUX2} \times \frac{N_2}{N_1} = 0.1\ A \quad (77)$$

Therefore, $\Delta I_{L(AUX)} = 0.1$ A. Use Equation 78 to calculate the minimum inductor value for the auxiliary supply.

$$L_{AUX} = \frac{V_{IN(max)} - V_{AUX1}}{\Delta I_{L(AUX)} \times f_{SW\_AUX}} \times \frac{V_{AUX1}}{V_{IN(max)}} = 132\ \mu H \quad (78)$$

Select a higher value of 150 µH to ensure the high-side switch current doesn't exceed the minimum peak current limit threshold.

8.2.2.12 Auxiliary Feedback Resistors

The two feedback resistors are selected to set the primary output voltage V_{AUX1} of the auxiliary supply. The internal reference for the off-state and on-state auxiliary output voltage levels are 1.4 V and 1 V, respectively. The feedback resistors are calculated such that both of the off-state and on-state auxiliary output voltage fall into the recommended operating range (8.5 V to 14 V). In this design example, the off-state and on-state auxiliary output voltages are set to 12.6 V and 9 V, respectively. R_{FB1} is selected to be 1 kΩ and R_{FB2} is calculated to be 8 kΩ according to Equation 79. Note that it is the valley of the output voltage that is regulated at the reference value. Therefore the average output voltage is greater than the reference value due to the ripple injected to the feedback node. R_{FB2} is selected to be 7.5 kΩ in this design example.

$$V_{AUX1} = V_{REF\_AUX} \times \left(1 + \frac{R_{FB2}}{R_{FB1}}\right) \quad (79)$$

8.2.2.13 R_{ON} Resistor

Use Equation 45 to calculate the value of R_{ON} required to achieve the desired switching frequency for the auxiliary supply. For this design example where the on-state V_{AUX1} is 9 V and f_{SW_AUX} is 600 kHz, the calculated value of R_{ON} is 167 kΩ. A standard value of 165 kΩ is selected for R_{ON}.

8.2.2.14 VIN Pin Capacitor

Place the required bypass capacitor close to the VIN pin of the LM5036 device. Ensure that the capacitance is large enough to limit the ripple of the VIN pin voltage to a desired level. Use Equation 80 to calculate the value of C_{IN} required to meet the ripple voltage ΔV_{IN} requirement.

$$C_{IN} \geq \frac{I_{AUX(max)}}{4 \times f_{SW\_AUX} \times \Delta V_{IN}} \quad (80)$$

Choosing a value of 0.5 V for ΔV_{IN} yields a minimum C_{IN} value of 0.067 µF. Select the standard value of 0.1 µF for this design. Ensure that the voltage rating of the input capacitor is greater than the maximum input voltage under all conditions.

8.2.2.15 Auxiliary Primary Output Capacitor

Use Equation 81 to calculate output ripple voltage for a conventional buck converter.

$$\Delta V_{AUX1} = \frac{\Delta I_{L(AUX)}}{8 \times f_{SW\_AUX} \times C_{AUX1}} \quad (81)$$

To limit the primary output ripple voltage ΔV_{AUX1} to approximately 50 mV, an output capacitor C_{AUX1} of 0.33 µF is required.

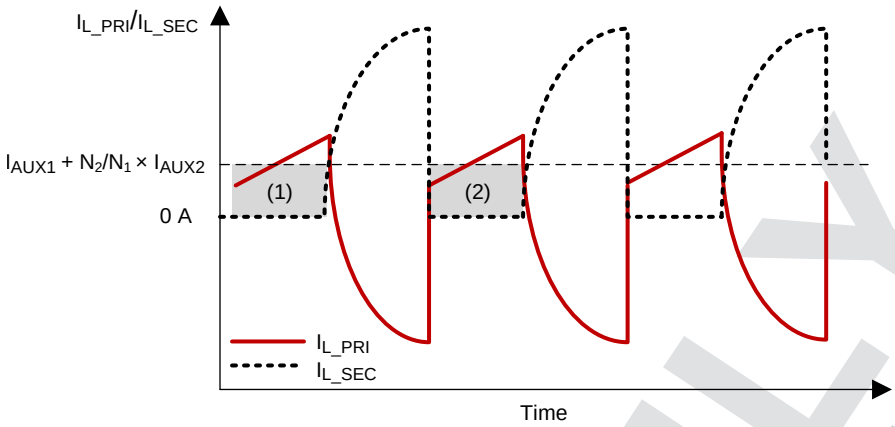


Figure 50. Auxiliary Transformer Current Waveform for C_{AUX1} Ripple Calculation

Figure 50 shows the primary and secondary winding current waveform I_{L_PRI} and I_{L_SEC}. The reflected secondary winding current adds to the primary winding current during the off-time of the high-side switch. Because of this increased current, the output voltage ripple is not the same as in conventional buck converter. The output capacitor value calculated in Equation 81 should be used as a starting point. Optimization of output capacitance over the entire line and load range must be done experimentally. If the majority of the load current is drawn from the secondary isolated output, a better approximation of the primary auxiliary output voltage ripple is given by Equation 82.

$$\Delta V_{AUX1} = \frac{\left(I_{AUX2} \times \frac{N_2}{N_1}\right) \times t_{ON\,(max)}}{C_{AUX1}} \tag{82}$$

A standard 1-µF, 25-V capacitor is selected for this design.

8.2.2.16 Auxiliary Secondary Output Capacitor

A simplified waveform for the secondary winding current I_{L_SEC} is shown in Figure 51.

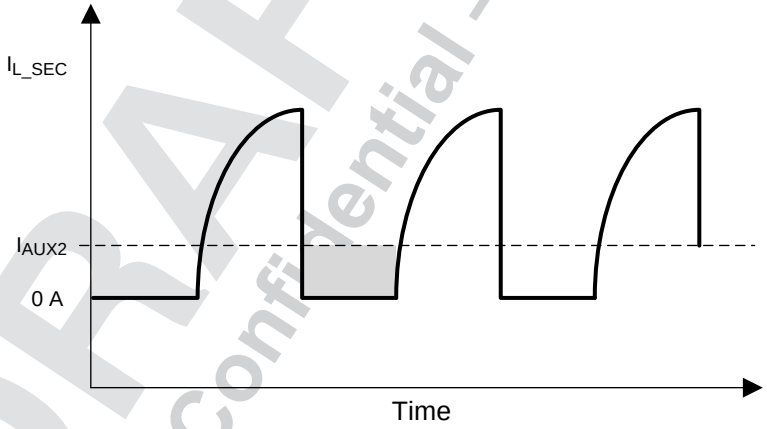


Figure 51. Auxiliary Transformer Secondary Winding Current Waveforms for C_{AUX2} Ripple Calculation

The secondary output current I_{AUX2} is sourced by C_{AUX2} during on-time of the high-side switch, T_{ON}. Ignoring the current transition times in the secondary winding, the secondary output capacitor ripple voltage can be calculated using Equation 83.

$$\Delta V_{AUX2} = \frac{I_{AUX2} \times t_{ON\,(max)}}{C_{AUX2}} \tag{83}$$

For a 1:1 auxiliary transformer turns ratio, the primary and secondary voltage ripple equations are identical. Therefore, C_{AUX2} is chosen to be equal to C_{AUX1} (1 µF) to achieve comparable ripple voltages on the primary and secondary outputs.

8.2.2.17 Auxiliary Feedback Ripple Circuit

Type I and Type II ripple circuits use series resistance and the triangular inductor ripple current to generate ripple at V_{AUX1} and the FB_AUX pin. The primary ripple current of a fly-buck is the combination of primary and reflected secondary currents as illustrated in Figure 50. In the fly-buck topology, Type I and Type II ripple circuits suffer from large jitter as the reflected load current affects the feedback ripple.

Selecting the Type III ripple components using the Equation 53 from Type 3 will guarantee that the FB_AUX pin ripple is greater than the capacitive ripple from the primary output capacitor C_{AUX1}.

With C_r = 1000 pF and C_{ac} = 100 nF, the calculated value of R_r is 206 kΩ. This value provides the minimum ripple for stable operation. Select a smaller resistance to allow for variations in t_{ON}, primary output capacitor and other components.

8.2.2.18 Auxiliary Secondary Diode

Use Equation 84 to calculate the reverse voltage across secondary rectifier of the auxiliary supply when the high-side switch is on.

$$V_D = \frac{N_2}{N_1} \times V_{IN(max)} \tag{84}$$

For a maximum input voltage of 75 V and the 1:1 turns ratio of this design, select a schottky diode with a rating of 75-V or higher.

8.2.2.19 VCC Diode

A diode must be connected between the primary output V_{AUX1} and the VCC pin. When V_{AUX1} is more than one diode voltage drop greater than the internal V_{CC} voltage, the V_{CC} bias current is supplied from V_{AUX1}. This results in reduced power losses in the internal V_{CC} regulator, especially at high input voltage.

8.2.2.20 Opto-Coupler Interface

Figure 52 illustrates the opto-coupler interface for the main feedback control loop. The primary side of the opto-coupler is biased with REF voltage from LM5036 device. R_{OPTO} should be selected such that with the minimum error amplifier output, the comp current flowing into the COMP pin of the device is greater than 800 µA which corresponds to zero duty cycle, as given by Equation 85.

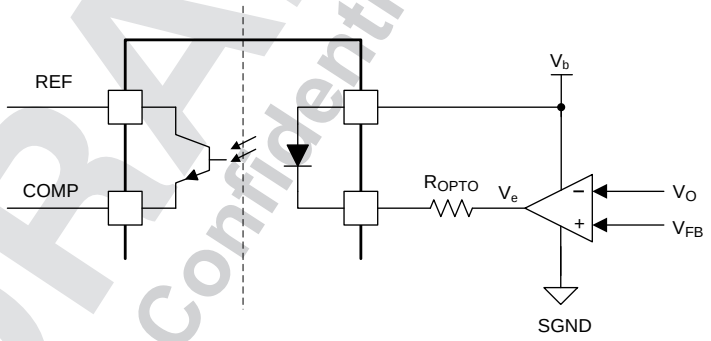


Figure 52. Opto-Coupler Interface

$$I_{COMP} = \frac{V_b - V_f - V_e}{R_{opto}} \times CTR$$

where

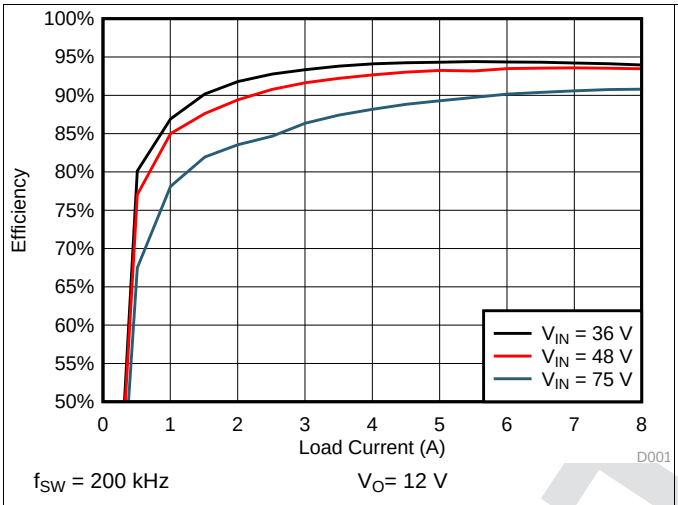
- where V_b is the bias supply for the error amplifier and opto-coupler on the secondary side
- V_f is the diode forward voltage drop of the opto-coupler
- V_e is the error amplifier output

- CTR is the current transfer ratio of the opto-coupler
- I_{COMP} is the comp current flowing into the COMP pin
- REF is the 5-V reference of LM5036 device (85)

8.2.2.21 Full-Bridge Converter Applications

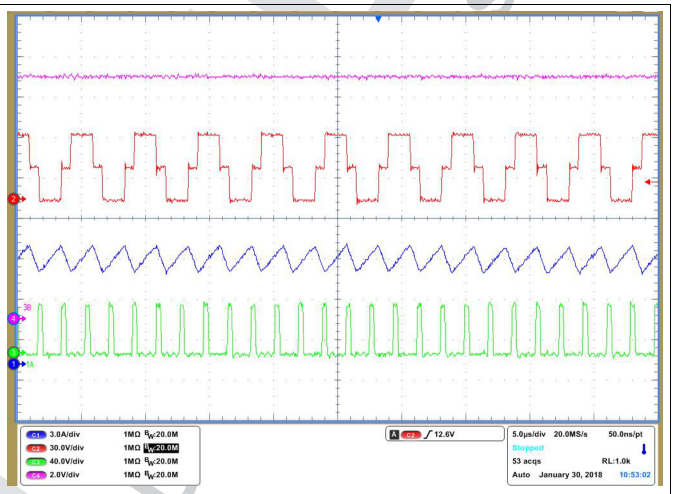
While LM5036 device is optimized for half-bridge applications, it can also be used for full-bridge applications. External gate drivers are needed to support an additional pair of FETs in full-bridge configuration. In addition, a DC-blocking capacitor is required to ensure voltage-second balance of the main transformer with the voltage-mode control of LM5036 device. Only one phase current information is needed for current protection in the full-bridge applications.

8.2.3 Application Curves



f_{SW} = 200 kHz V_O= 12 V

Figure 53. Efficiency



V_{IN} = 48 V V_O = 12 V
I_O = 8 A

Figure 54. Steady State Operation Waveform

9 Power Supply Recommendations

The power converter controlled by LM5036 device can have considerable current level. Care should be taken that components with the correct current rating are chosen. This includes magnetic components, power MOSFETS and diodes, connectors and wire sizes. Input and output capacitors should have the correct ripple current rating.

The recommended maximum input voltage for the VIN pin of LM5036 device is 100 V. The recommended voltage for the VCC pin is between 8.5 V and 14 V. Both VCC pin and REF pin must be locally decoupled with a ceramic capacitor. The recommended range of values is 0.47 µF to 10 µF for VCC pin, and 0.1 µF to 10 µF for REF pin. To reduce the power consumption of the internal VCC regulator, an external bias supply can be connected to VCC pin through a diode.

10 Layout

10.1 Layout Guidelines

- The two ground planes (AGND and PGND) of LM5036 device should be tied together with a short and direct connection to avoid jitter due to relative ground bounce. The connection point could be at the negative terminal of the input power supply.
- The VIN, VCC, REF pin capacitors, and CS_NEG resistor should be tied to PGND plane. UVLO, ON_OFF, RT, RON, RD1 and RD2 resistors, RAMP, RES, SS and SSSR capacitors, and the thermal pad should all be tied to AGND plane.
- SW and SW_AUX are switching nodes which switch rapidly between VIN and GND every cycle which are sources of high dv/dt noise. Therefore, large SW/SW_AUX node area should be avoided.
- The differential current sense signals at CS_POS and CS_NEG pins should be routed in parallel and close to each other to minimize the common-mode noise.
- The area of the loop formed by the main feedback control signal traces (COMP and REF) should be minimized in order to reduce the noise pick up. This can be accomplished by placing the COMP and REF signal traces on top of each other in adjacent PCB layers. In addition, the main feedback control signal traces should be routed away from the SW_AUX switching node to avoid high dv/dt noise coupling.
- The gate drive outputs (LSG and HSG) should have short and direct paths to the power MOSFETs to minimize parasitic inductance in the gate driving loop.
- The VCC and REF decoupling capacitors should be placed close to their respective pins with short trace inductance. Low ESR and ESL ceramic capacitors are recommended for the boot-strap, VCC and the REF capacitors.
- A decoupling capacitor should be placed close to the IC, directly across VIN and PGND pins. The connections to these two pins should be direct to minimize the loop area which carries switching currents.
- The boot-strap capacitors required for the high-side gate drivers of the half-bridge converter and auxiliary supply should be located close to the IC and connected directly to the BST/BST_AUX and SW/SW_AUX pins.
- The area of the switching loop of the power stage consisting of input capacitor, capacitive divider, transformer, and the primary MOSFETs should be minimized.

10.2 Layout Example

See Figure 55 for an example layout that matches the schematic of Figure 41.

Layout Example (continued)

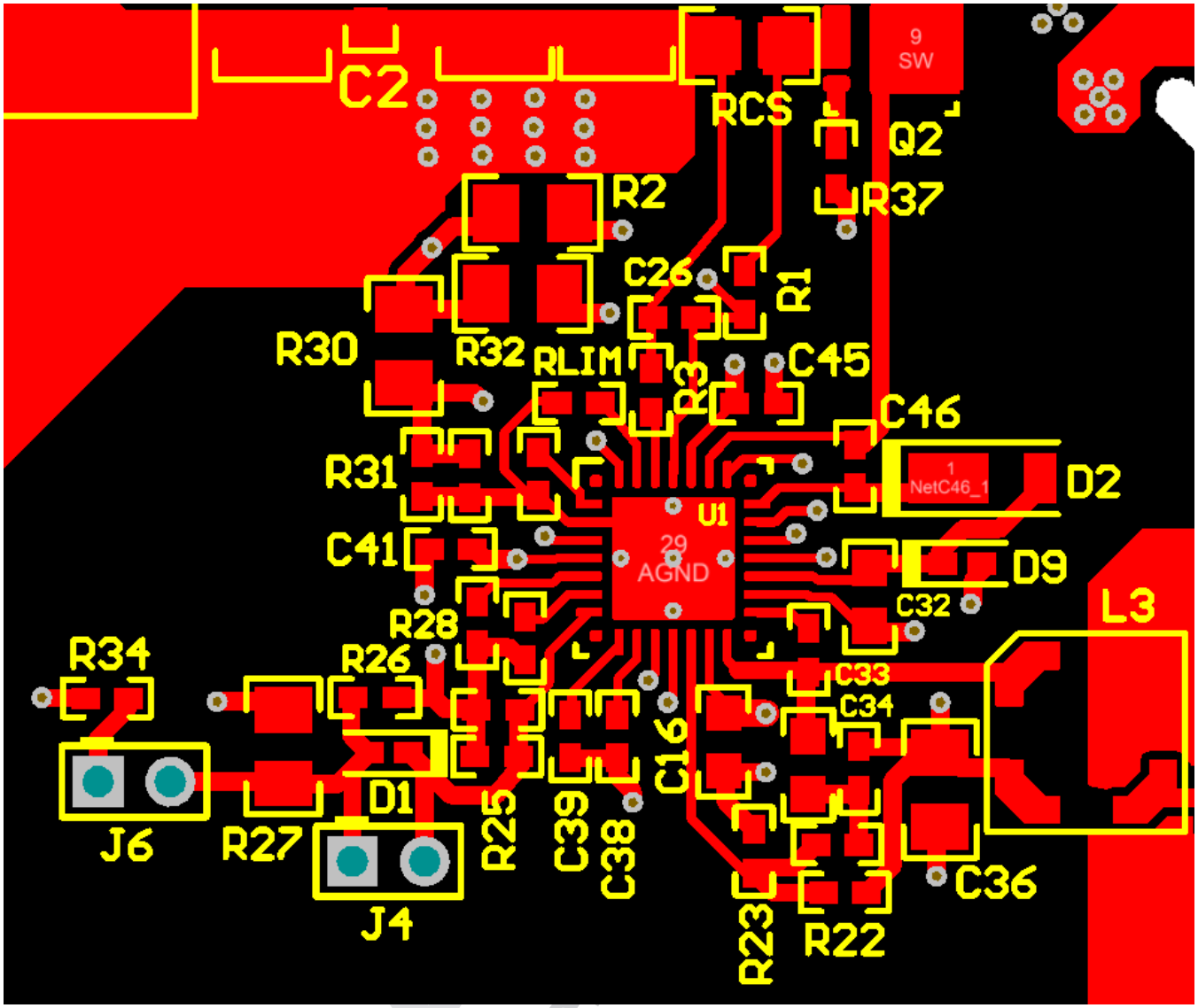


Figure 55. LM5036 PCB Layout Example

11 Device and Documentation Support

11.1 Custom Design With WEBENCH® Tools

Click here to create a custom design using the LM5036 device with the WEBENCH® Power Designer.

1. Start by entering the input voltage (V_{IN}), output voltage (V_{OUT}), and output current (I_{OUT}) requirements.
2. Optimize the design for key parameters such as efficiency, footprint, and cost using the optimizer dial.
3. Compare the generated design with other possible solutions from Texas Instruments.

The WEBENCH Power Designer provides a customized schematic along with a list of materials with real-time pricing and component availability.

In most cases, these actions are available:

- Run electrical simulations to see important waveforms and circuit performance
- Run thermal simulations to understand board thermal performance
- Export customized schematic and layout into popular CAD formats
- Print PDF reports for the design, and share the design with colleagues

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ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

11.6 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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